



University of
Zurich^{UZH}

Physik-Institut

CMS Inner Detector

The Run 1 to Run 2 transition, and
first experience of Run 2

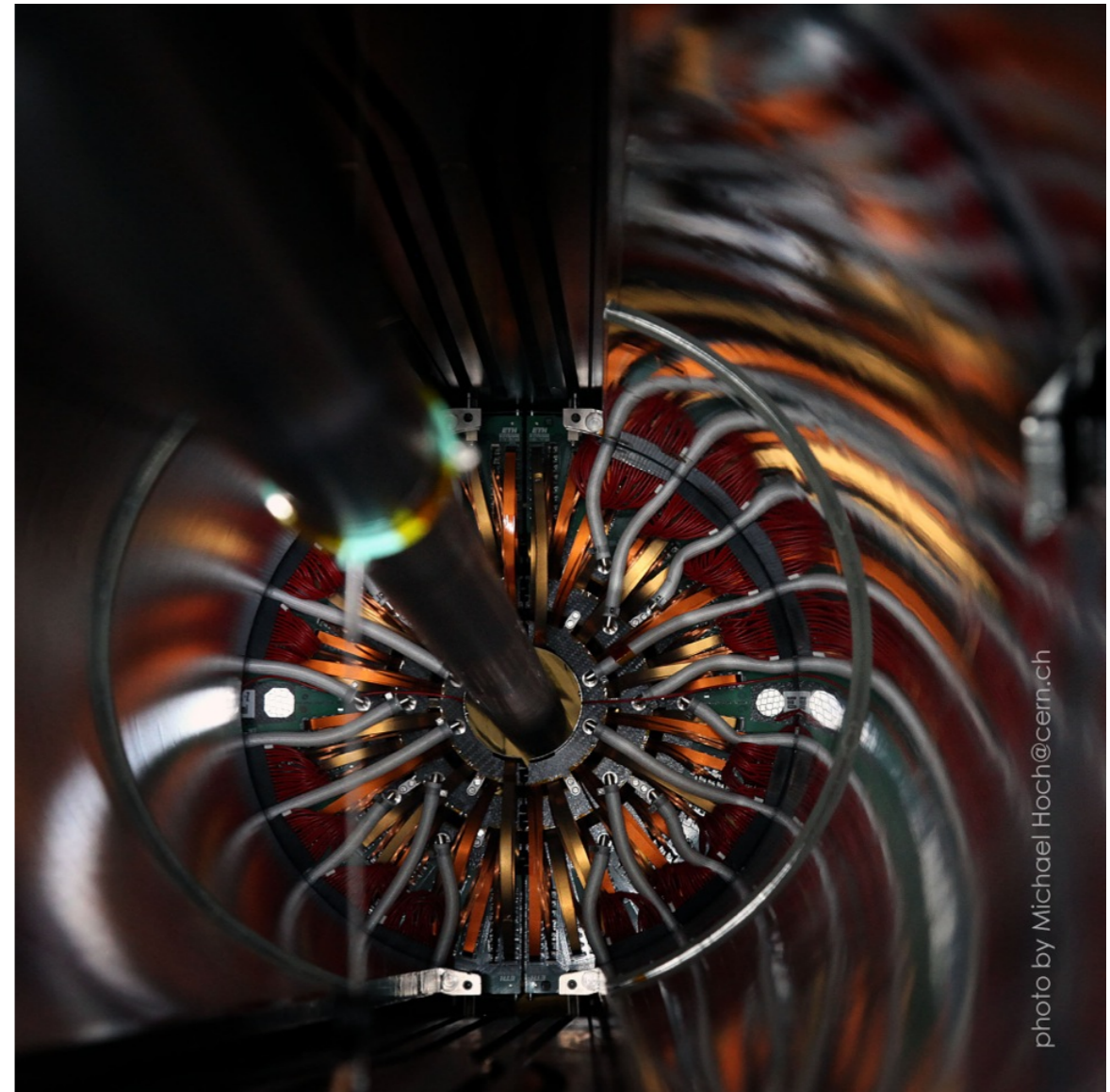


photo by Michael Hoch@cern.ch

Clemens Lange (UZH)
on behalf of the CMS collaboration
VERTEX 2015
Santa Fe, New Mexico, USA
1st June 2015



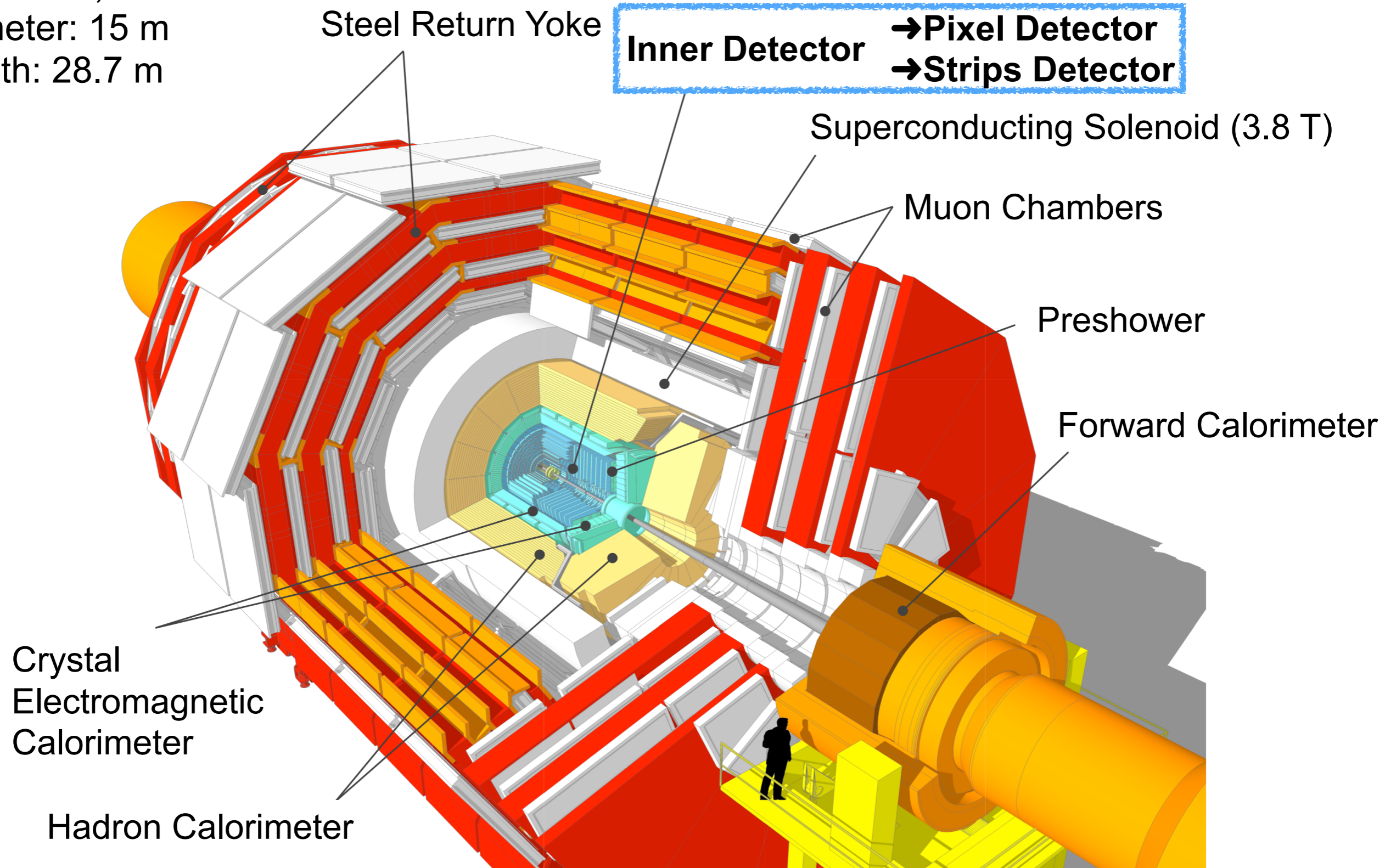


CMS Detector

Weight: 14,000 tonnes

Diameter: 15 m

Length: 28.7 m



CMS Pixel Detector

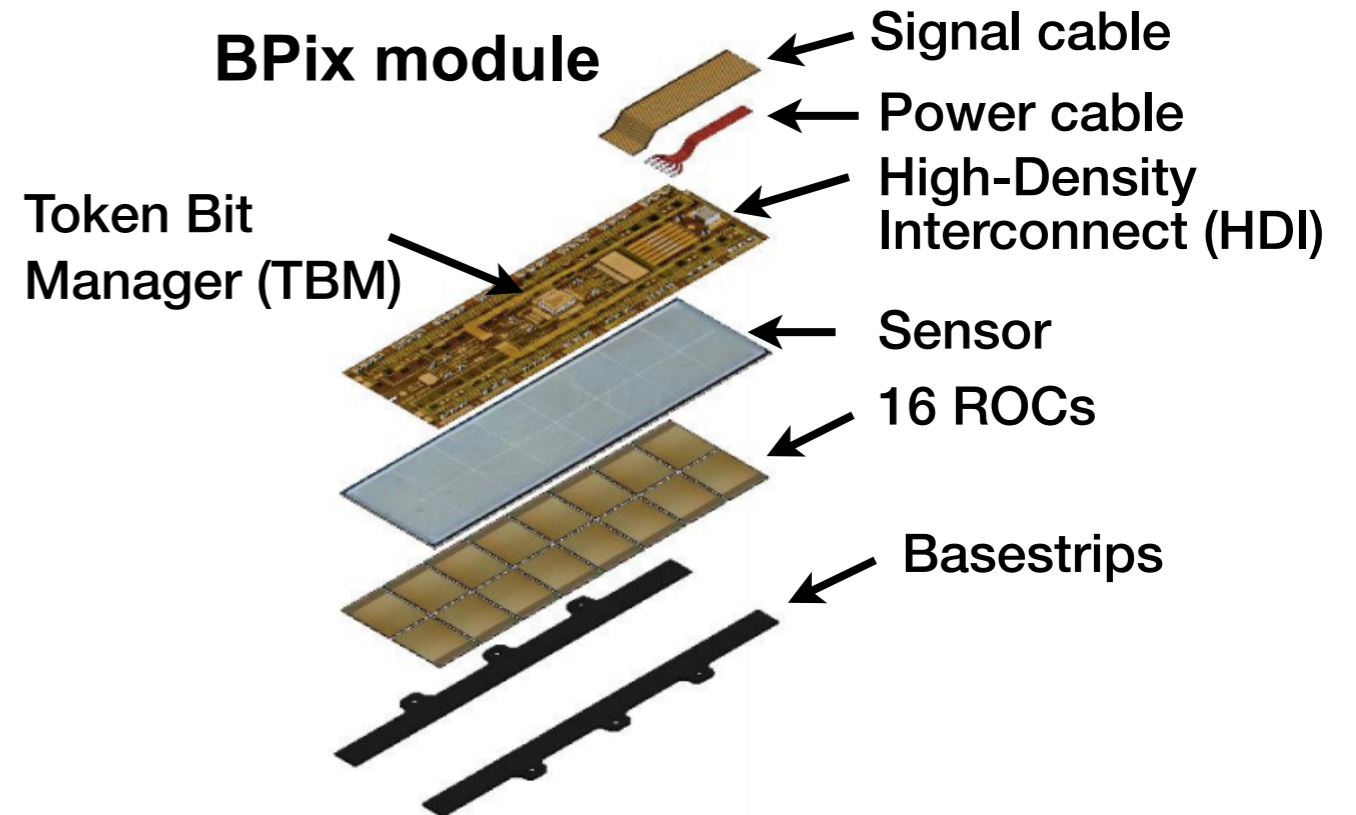
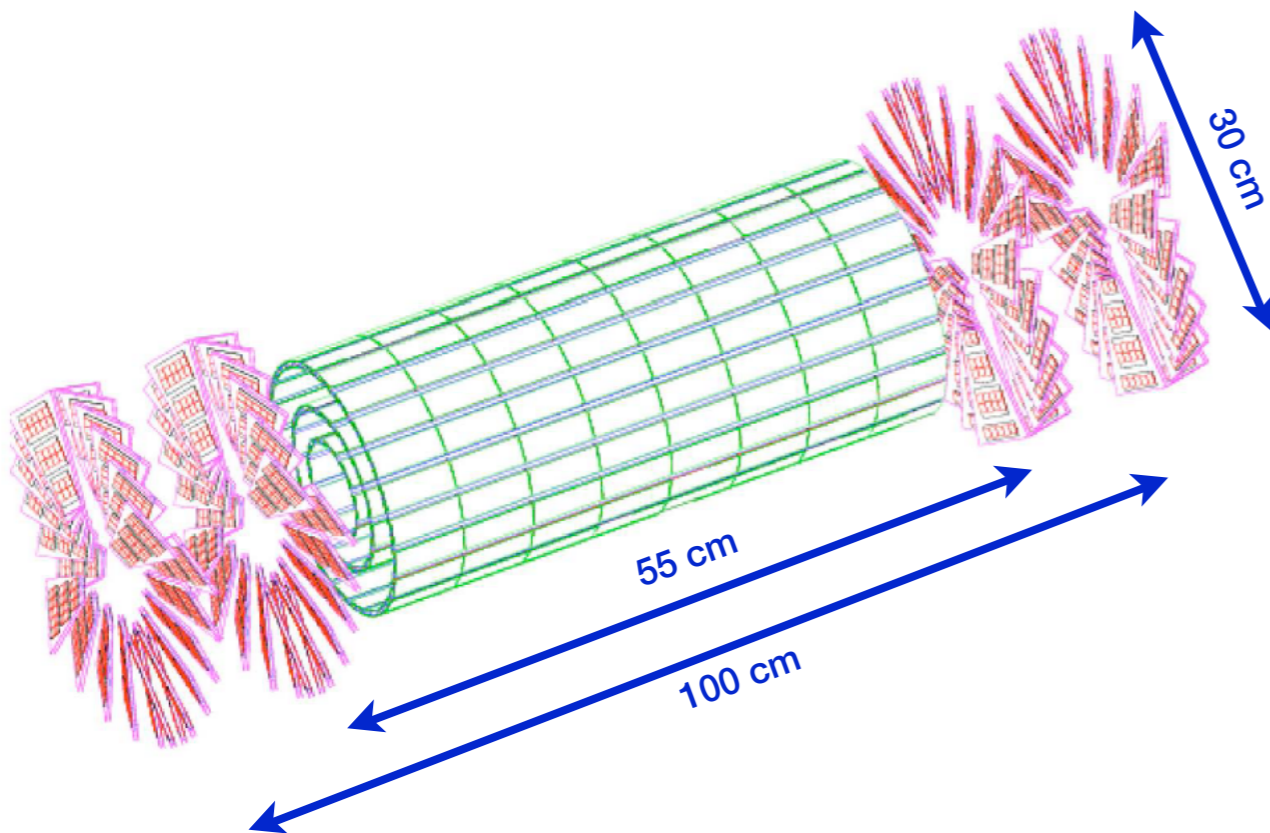
basic properties:

> 3 barrel layers (BPix)

- radii of 4.3, 7.2, and 11 cm
- 48 million pixels, area of 0.78 m²

> 2 endcap pixel disks at each side (FPix)

- 18 million pixels, area of 0.28 m²



> BPix: 768 modules

> FPix: 192 panels

> pixel size: 100 x 150 μm (250 μm sensor thickness)

> 1 ROC serves a 52 x 80 array of pixels

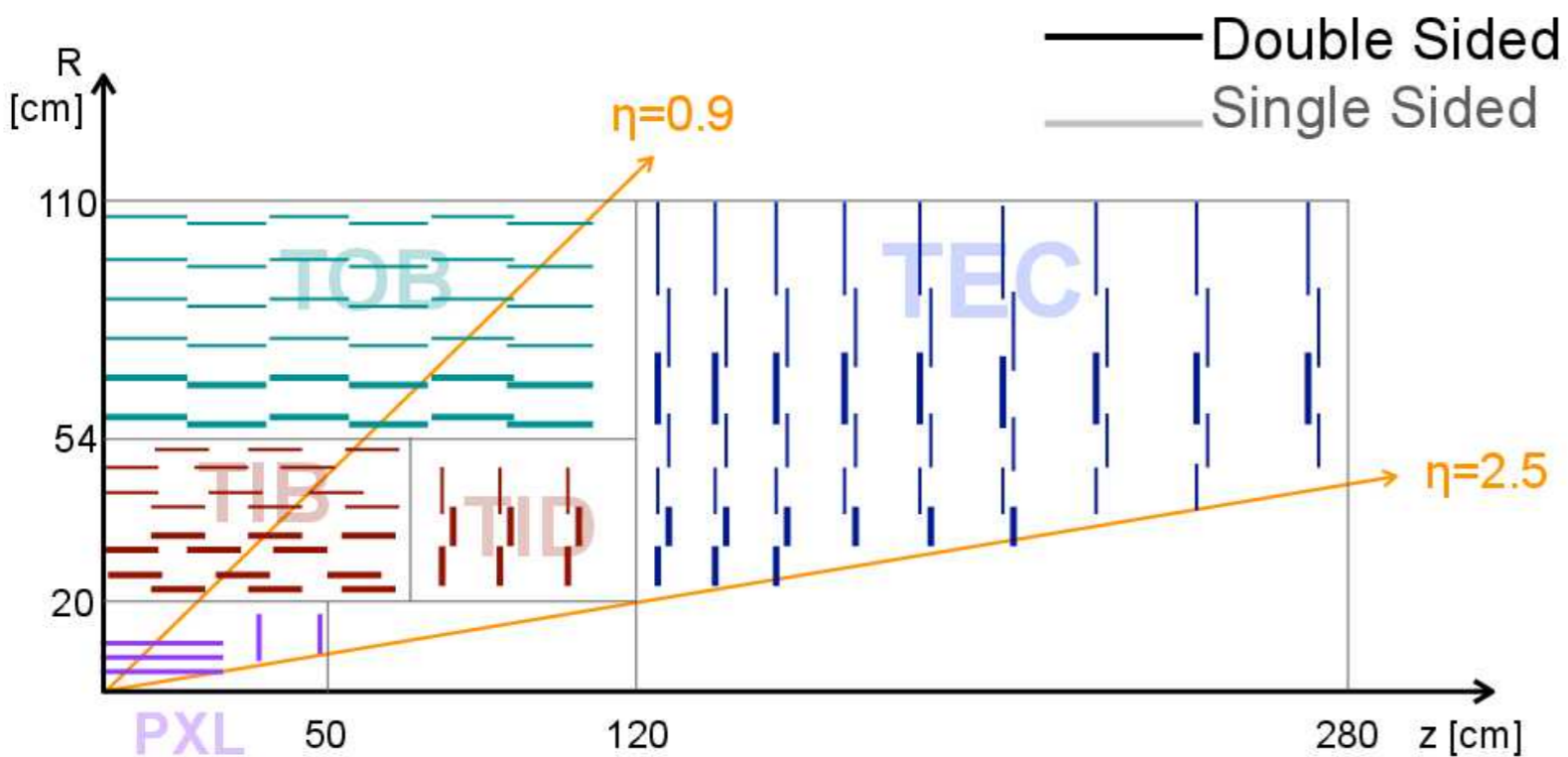
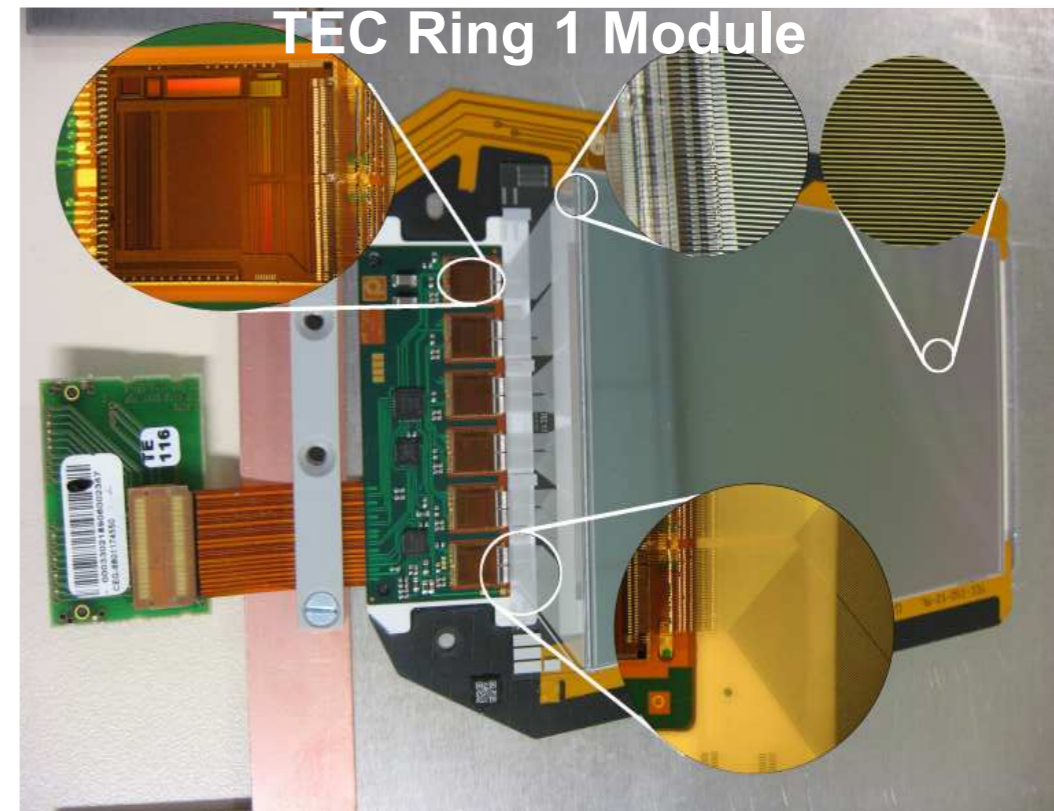
> sensor: n+ implant in n bulk

> ~66 million readout channels in total

CMS Silicon Strip Tracker

basic properties:

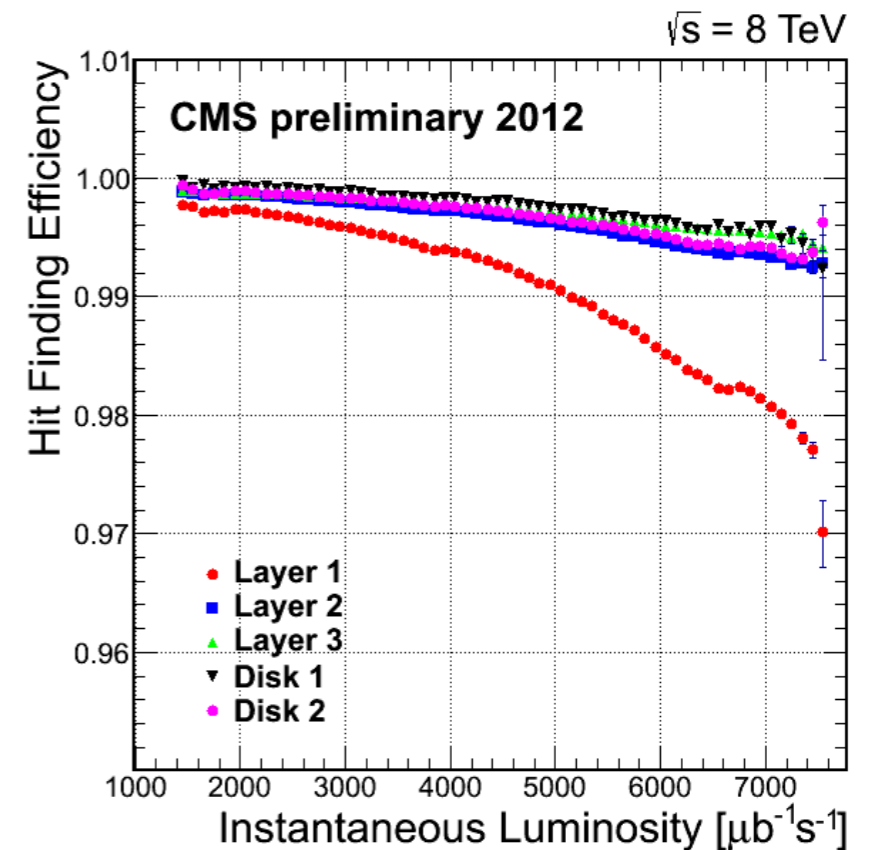
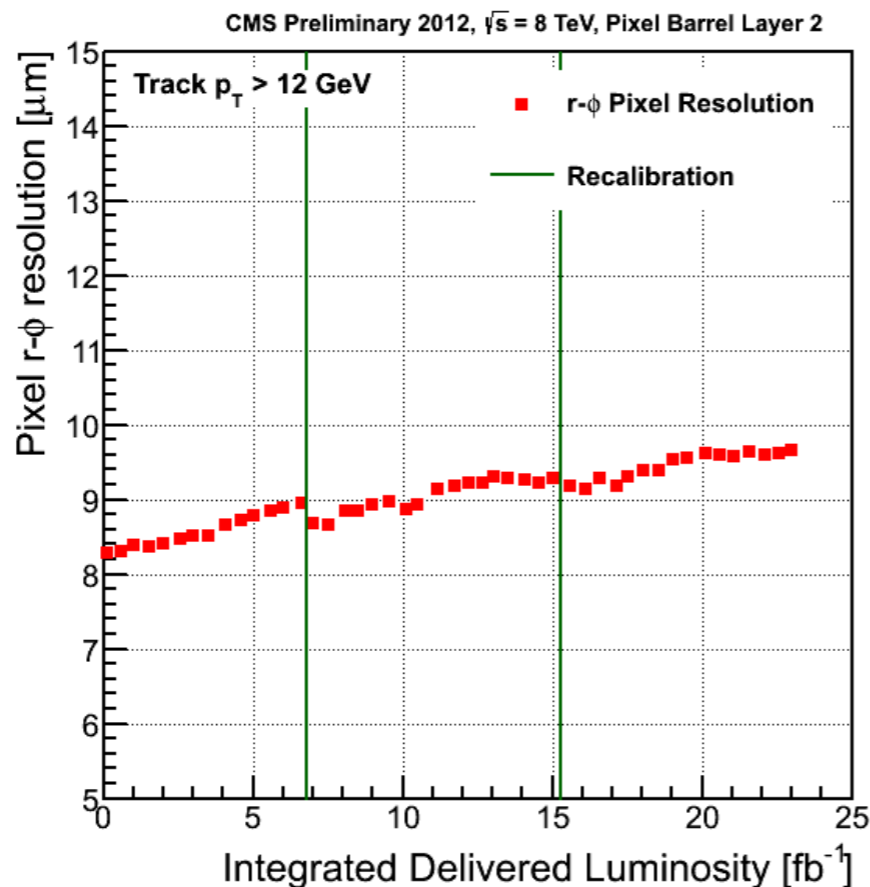
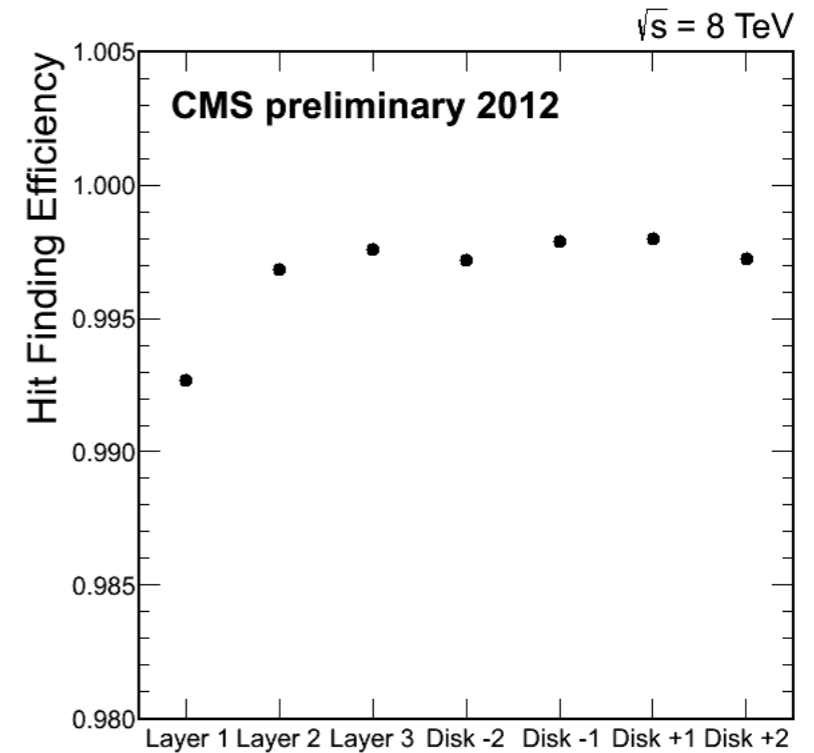
- > 10 layers in barrel region
 - 4 Inner Barrel (TIB), 6 Outer Barrel (TOB)
- > 9+3 discs in the inner disks (TID) and endcaps (TEC)
- > active area 200 m²
- > ~9.6 million electronic channels



- > p⁺-in-n silicon sensors
- > 320 μm and 500 μm thick
- > 512-768 strips
- > strip pitch 83-205 μm

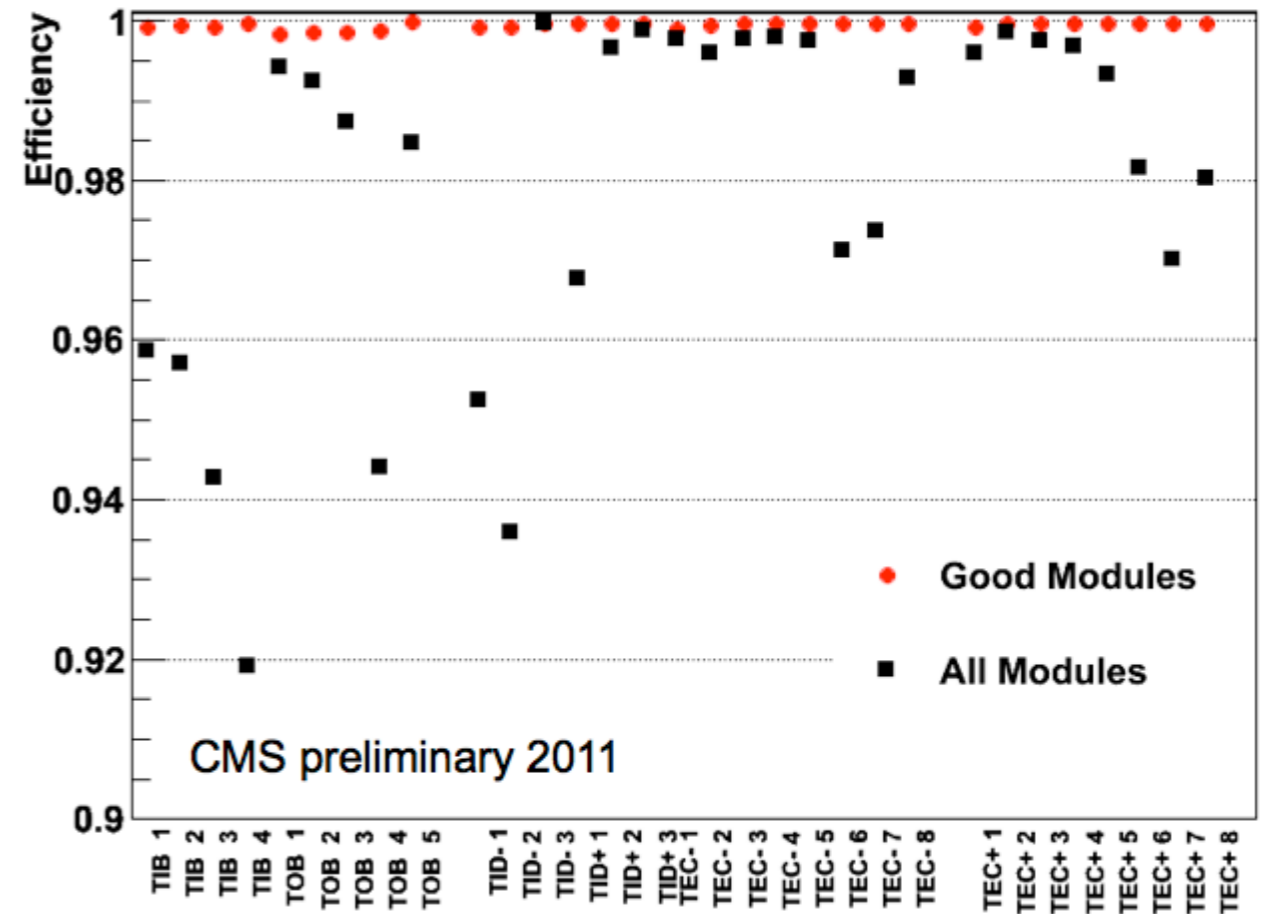
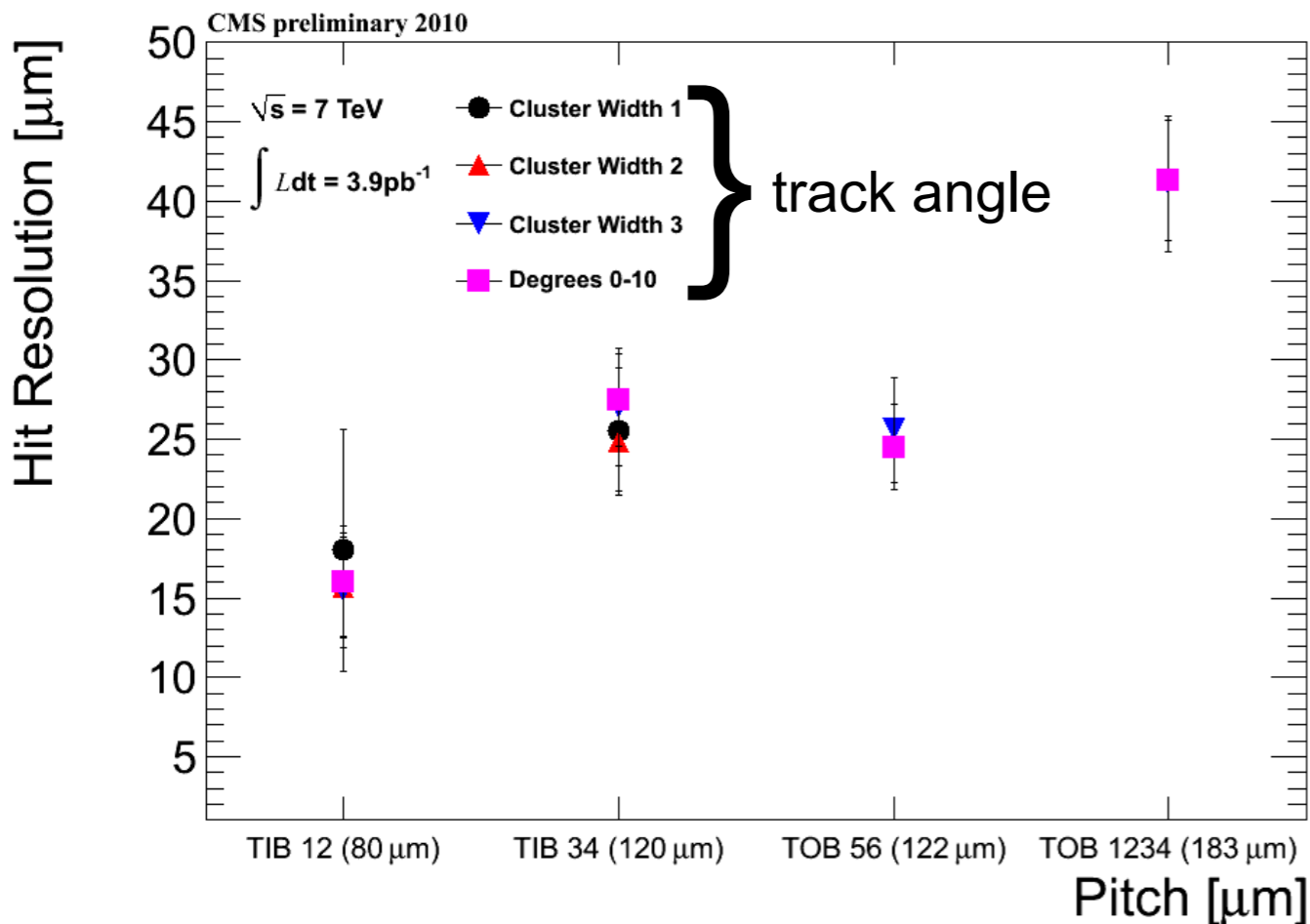
Performance of the Pixel Detector in Run 1

- > hit efficiency above 99% for all working ROCs
- > dynamic inefficiency observed with increasing instantaneous luminosity:
 - higher occupancy increases probability of ROC buffer overflow
- > measured r - ϕ resolution $< 10 \mu\text{m}$ at the end of Run 1



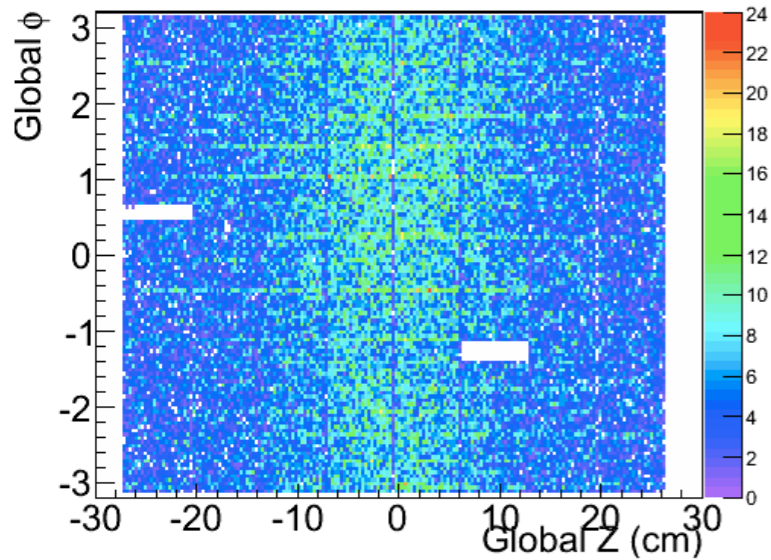
Performance of the Strips Tracker in Run 1

- > hit efficiency considering all modules: variations down to 92%
- > for good modules: > 99%

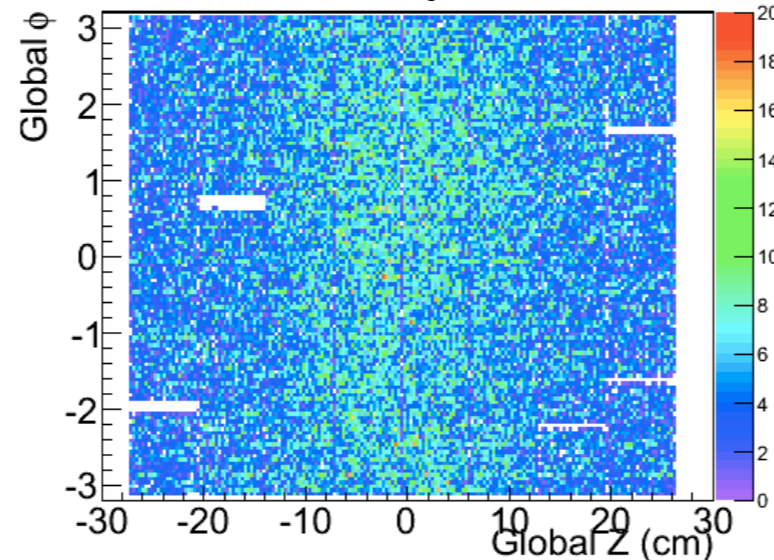


- > hit resolution: 16-42 μm depending on pitch

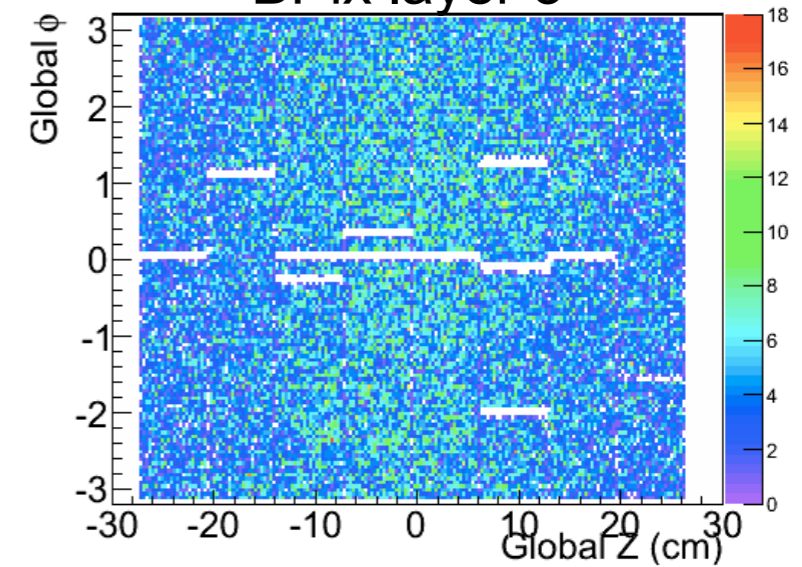
BPix layer 1



BPix layer 2



BPix layer 3

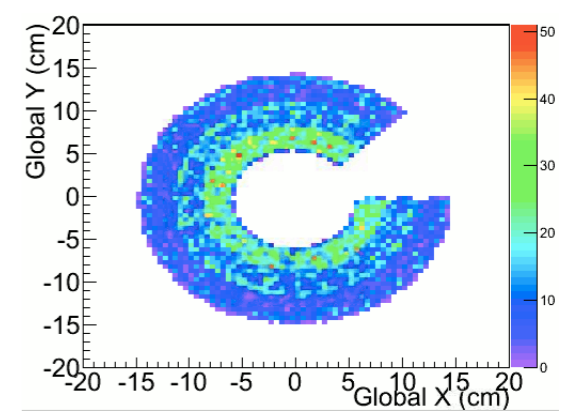
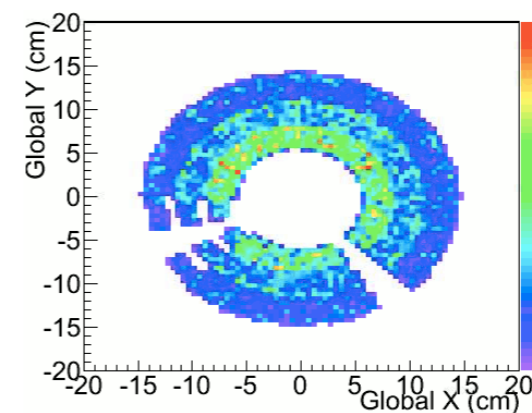
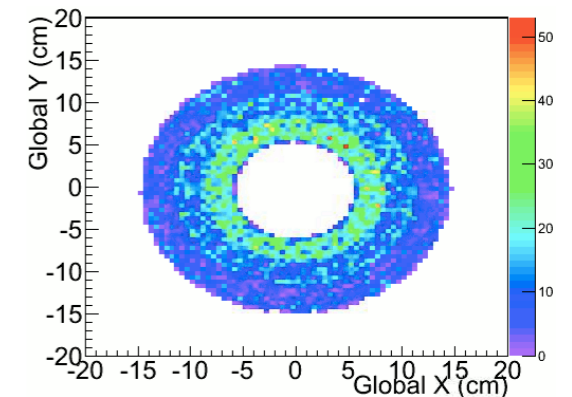
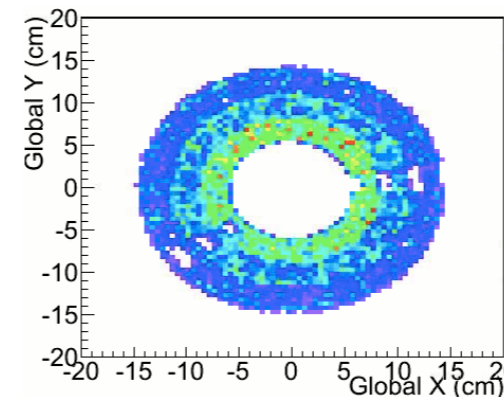


➤ BPix: ~2.3% of all channels not operational:

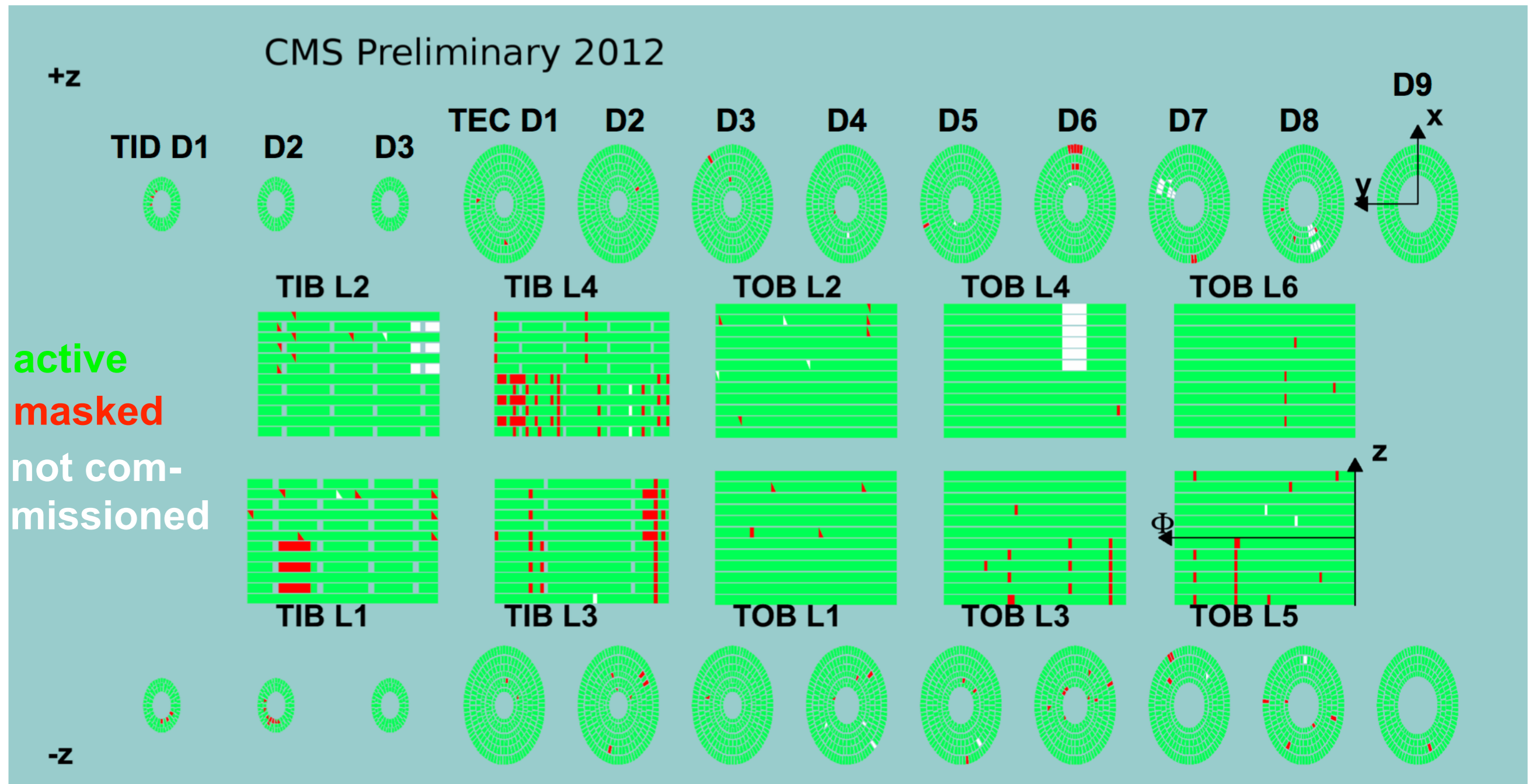
- broken wirebond connections between ROC and HDI, and laser and AOH
- modules with old ROC design

➤ FPix: ~7.8% non-operational:

- slow channels: long rise time in analog readout, pixel address misreading, miscounting of ROCs and events
- broken optical readout



Status of Strips Tracker after Run 1

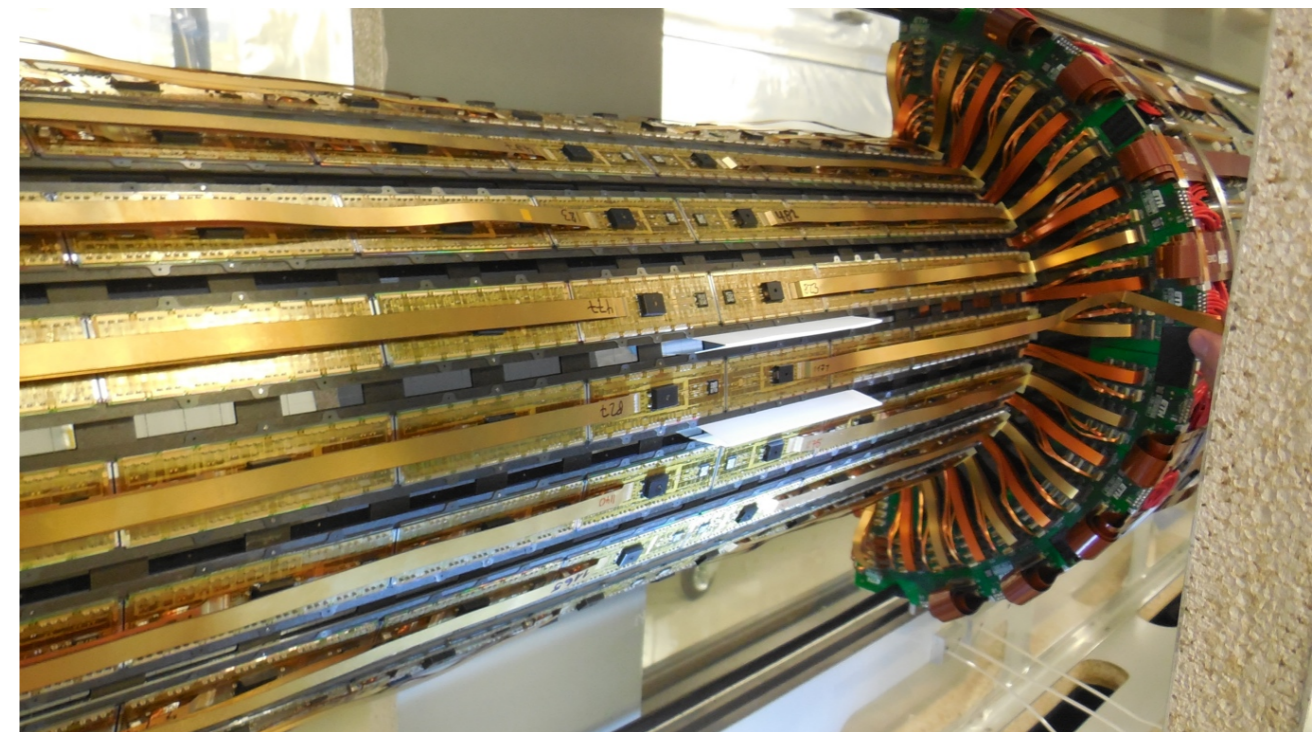
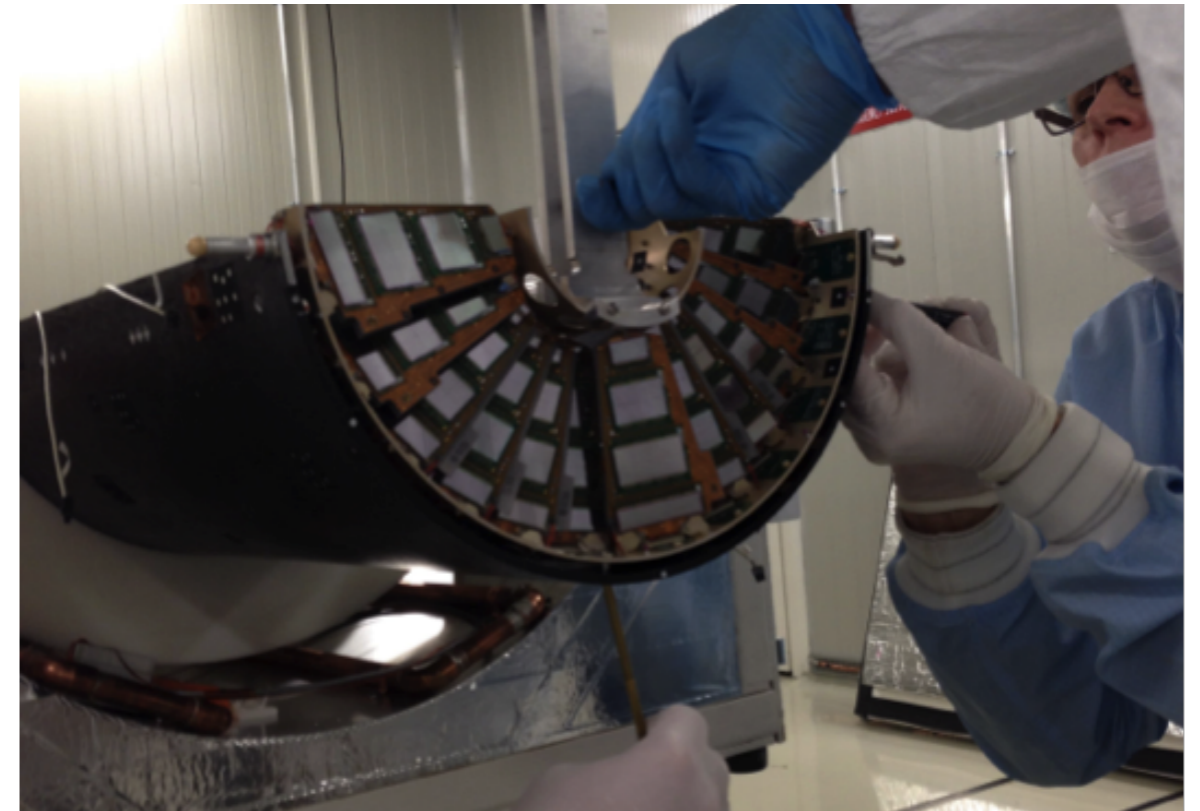


> 2.4% of strips tracker not active:

- control ring shorts/missing, HV line shorts/open, fibres...

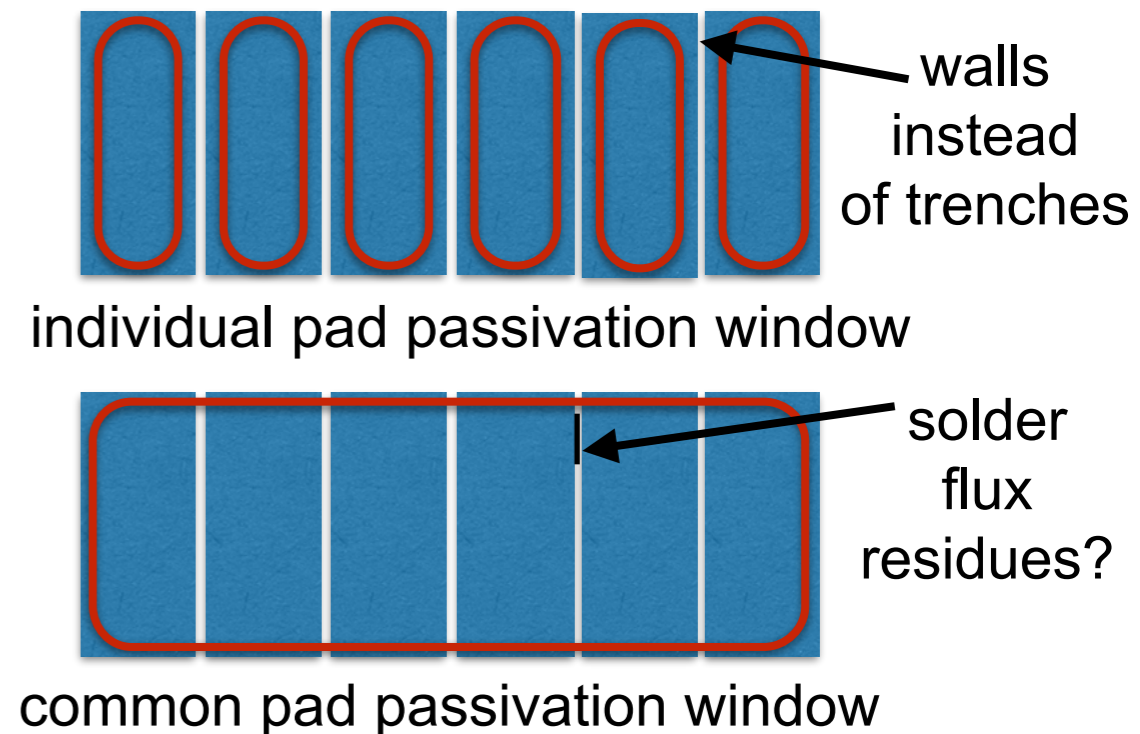
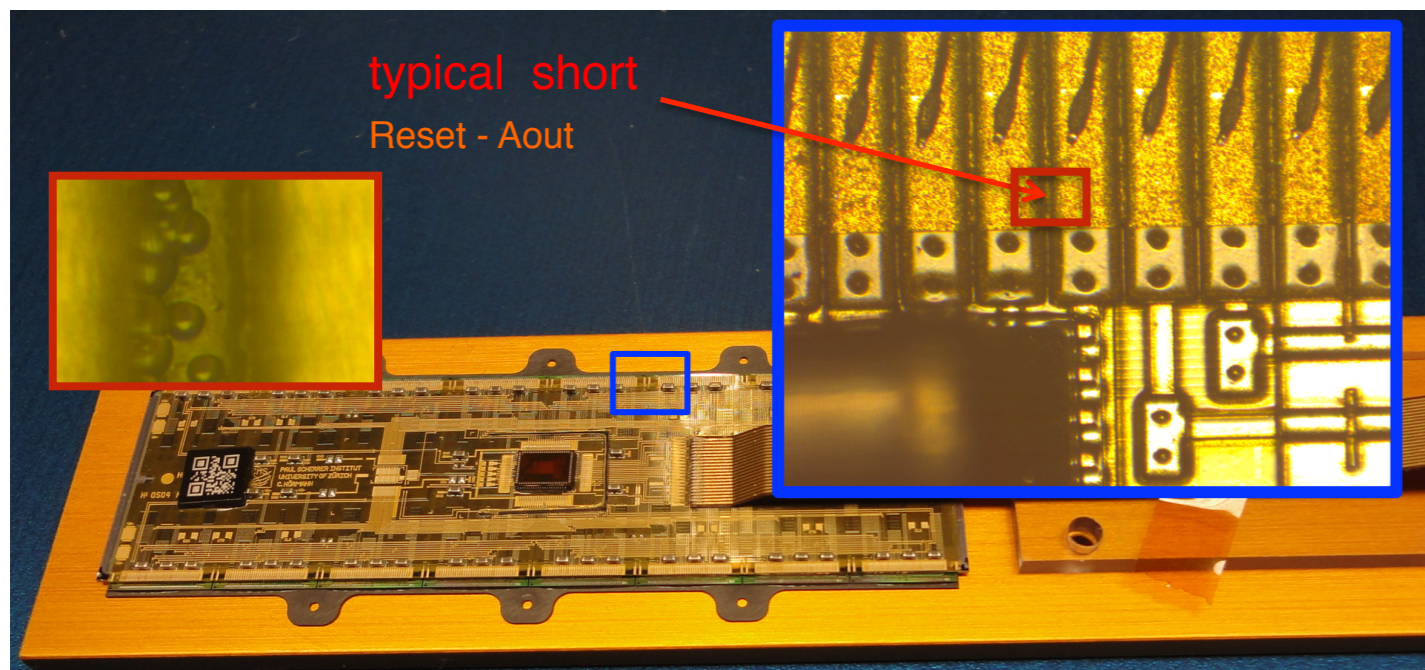
Repair of Pixel Detector on Surface

- pixel detector extracted from CMS in summer 2013
- FPix: 99.9% operational after repairs, issues fixed:
 - misaligned flex cables (46% of faulty channels)
 - unplugged analog electrical-to-optical converters (AOHs) - 40% of faulty channels
 - problematic panels (14%)
- BPix: replace only layer 3 outer shell (52% of faulty channels)
 - other layers and inner shell of layer 3 considered too risky to touch
 - 2 not fully operational AOHs replaced (so far workaround allowed data taking)
 - about 99% operational



Barrel Pixel Detector Quadrant Failure

- > in mid-August 2014, after having repaired a BPix module, tests of a quadrant show serious damage → 55 modules not working anymore
- > shorts found at ROC between two pins (mostly close to SMD components)
- > multiple shorted modules also TBM pads and cable pads
- > shorts suspected to be caused by humidity due to condensation in cooling box
- > detector repaired (40 new modules, 19 repaired) at PSI within 3 months thanks to availability of spare components, expertise, and good manufacturer relations



Operating at design temperatures

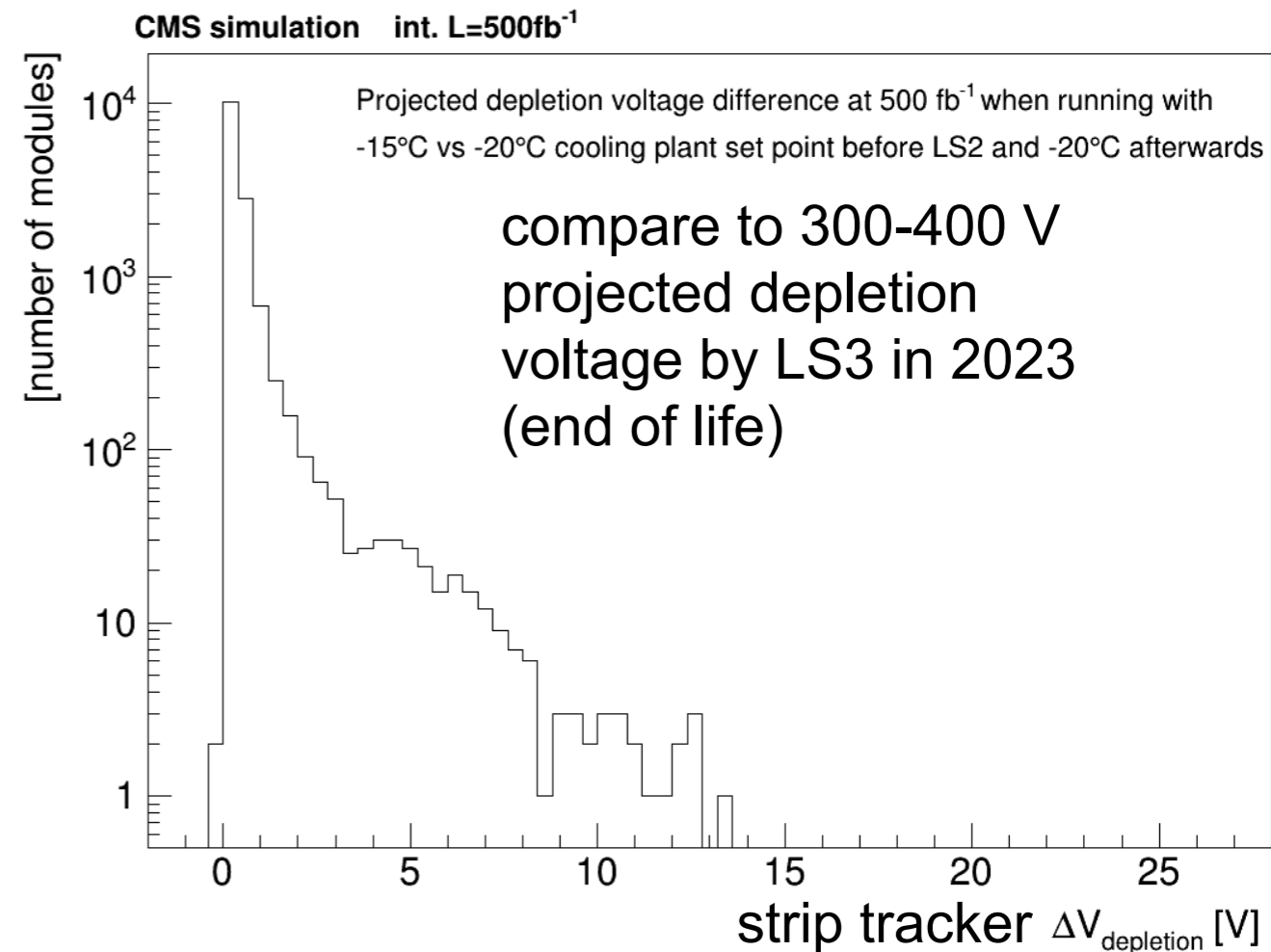
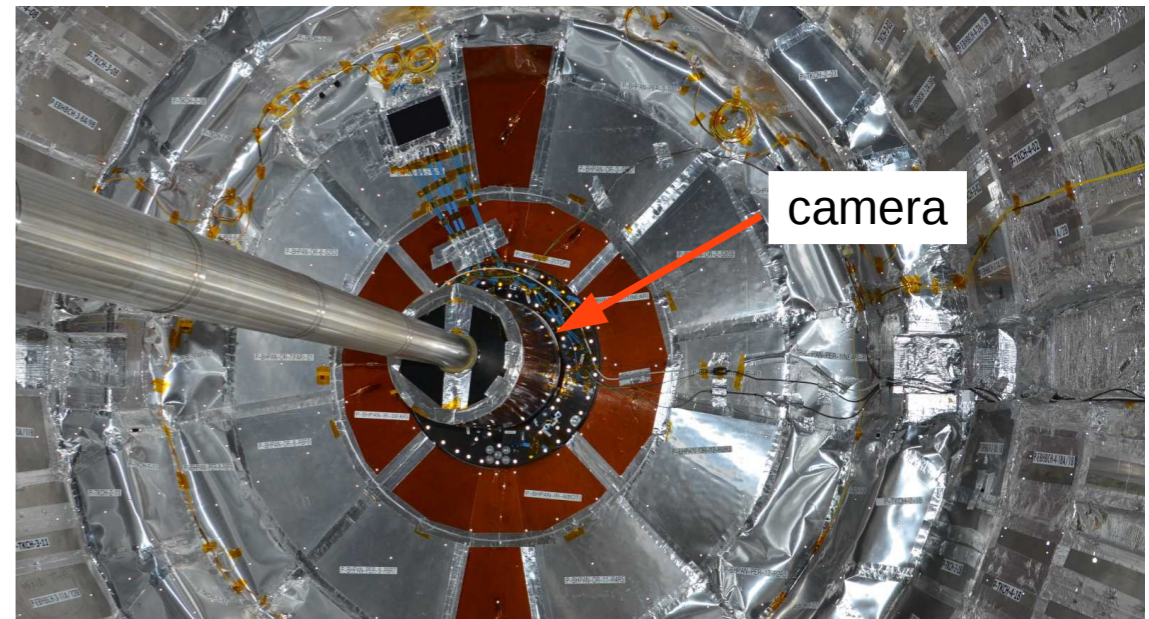
- > tracking detectors were designed to operate at low temperatures from the beginning (-20°C for pixel)
 - reduce sensor leakage currents (~50% lower every 8°C)
 - prevent reverse annealing (would require too high depletion voltage at some point)

- > dew points in tracker bulkhead and service channels not low enough
 - imperfect sealing

- > long shutdown (LS) 1 used to improve sealing, insulation, C₆F₁₄ cooling and dry gas plants

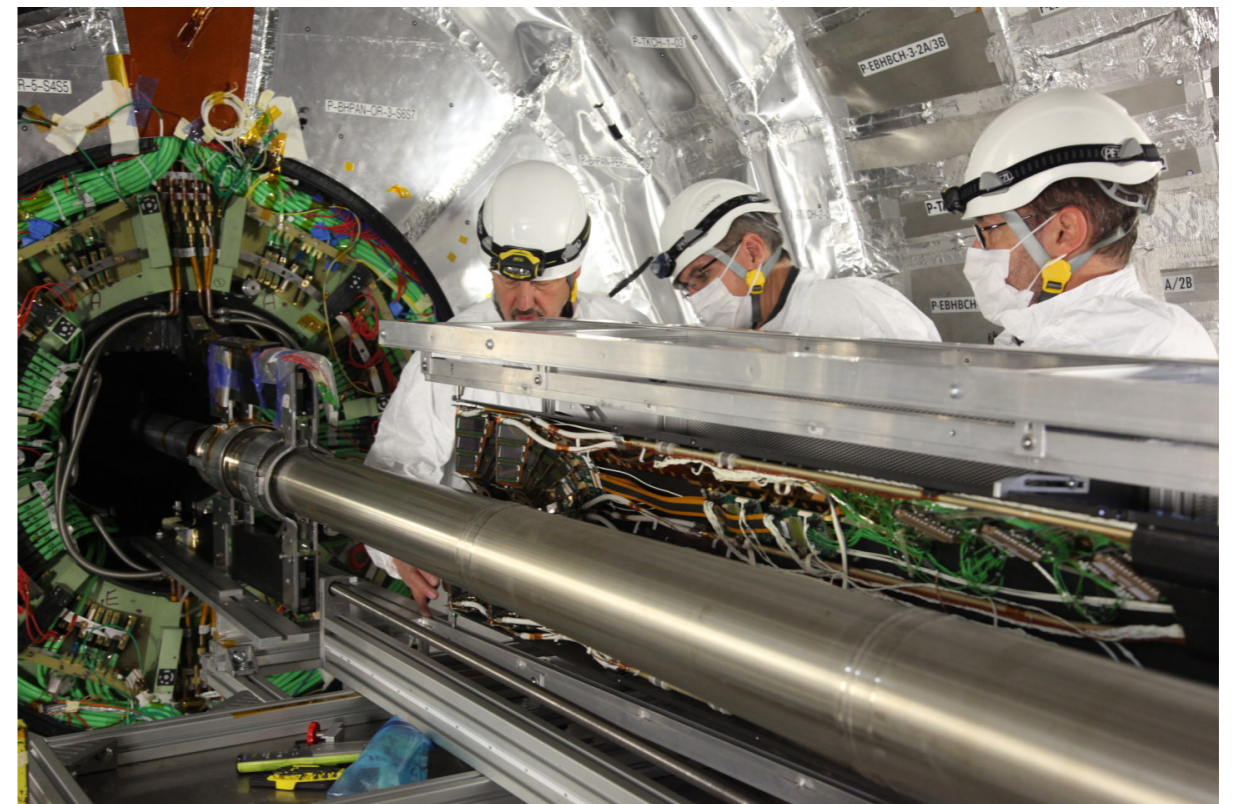
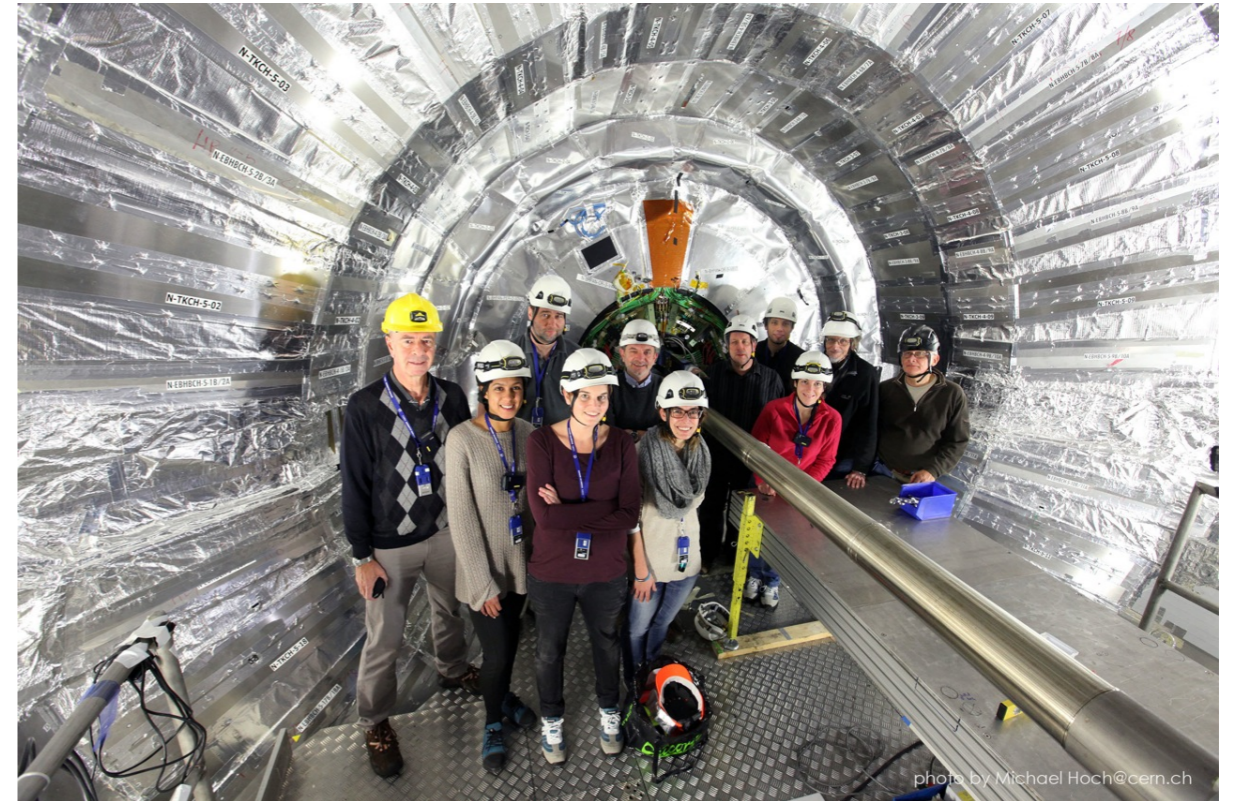
- > could now run at -20°C

- > decision to run at -15°C (-10°C for pixels) - safe until LS2 in 2018 ($\mathcal{L} \sim 150 \text{ fb}^{-1}$)



Re-insertion of the Pixel Detector

- BPix installed into CMS on 8th December 2014 (3 months later than planned)
 - centered w.r.t. new beampipe
- one day later:
 - cooling loops connected
 - Power cables + fibers connected
 - first attempt to power on and check one sector the same day
- 3 days for detector checkout at +16°C
- FPix installation on 13th December
- similar procedure as for BPix
- pilot system for Phase 1 upgrade installed (see B. Akgun's talk)
- most work finished before Christmas

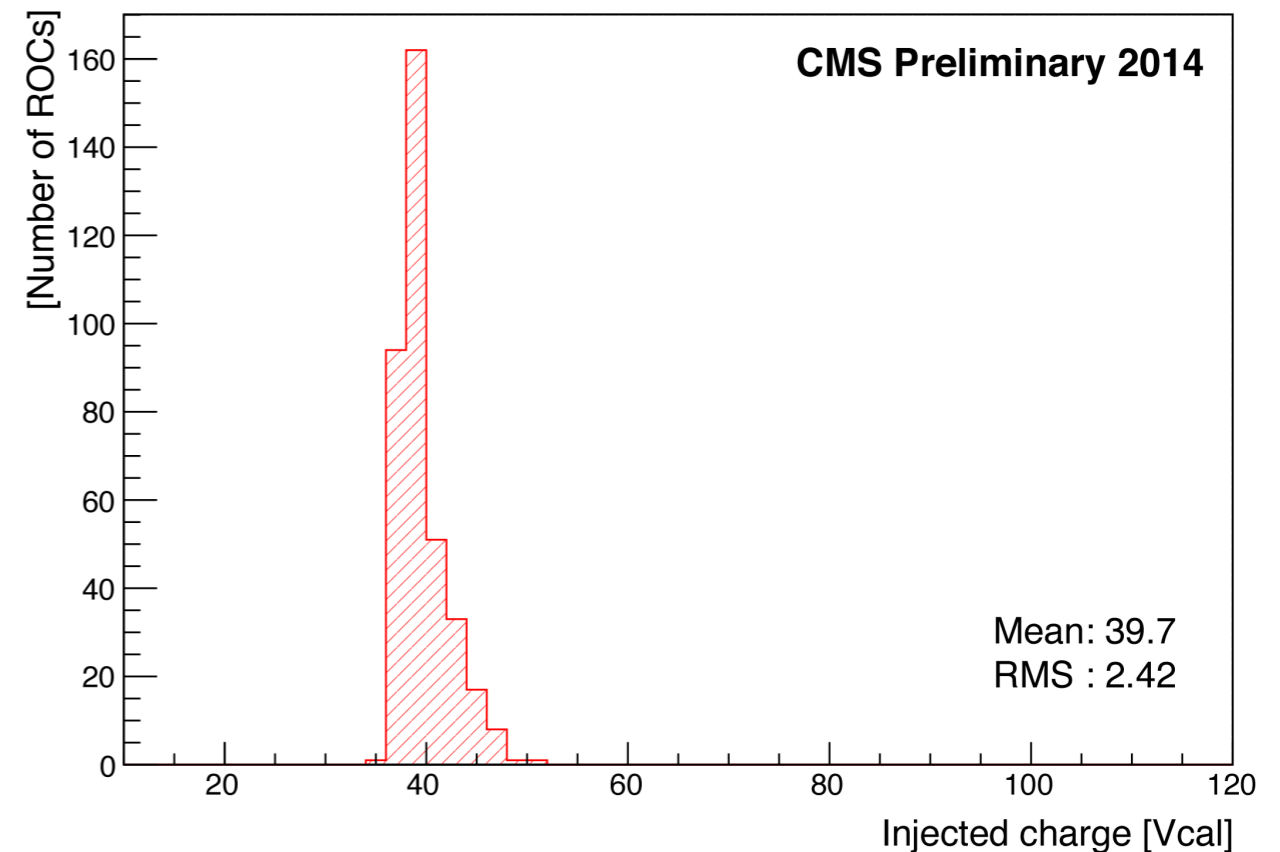




Re-commissioning of the Pixel Detector

- > pixel detector was re-commissioned in January 2015 within ~2 weeks
 - exercised and improved during LS1
 - basic set of calibrations
 - analog voltage for ROC (Vana) calibration
 - pixel comparator threshold calibration
 - pulse height optimisation
 - gain calibration
- > switch to new trigger and timing control system
- > tracker bulkheads closed on 29th January
- > BPix: ~1% disabled channels
- > FPix: 0.04% dead channels

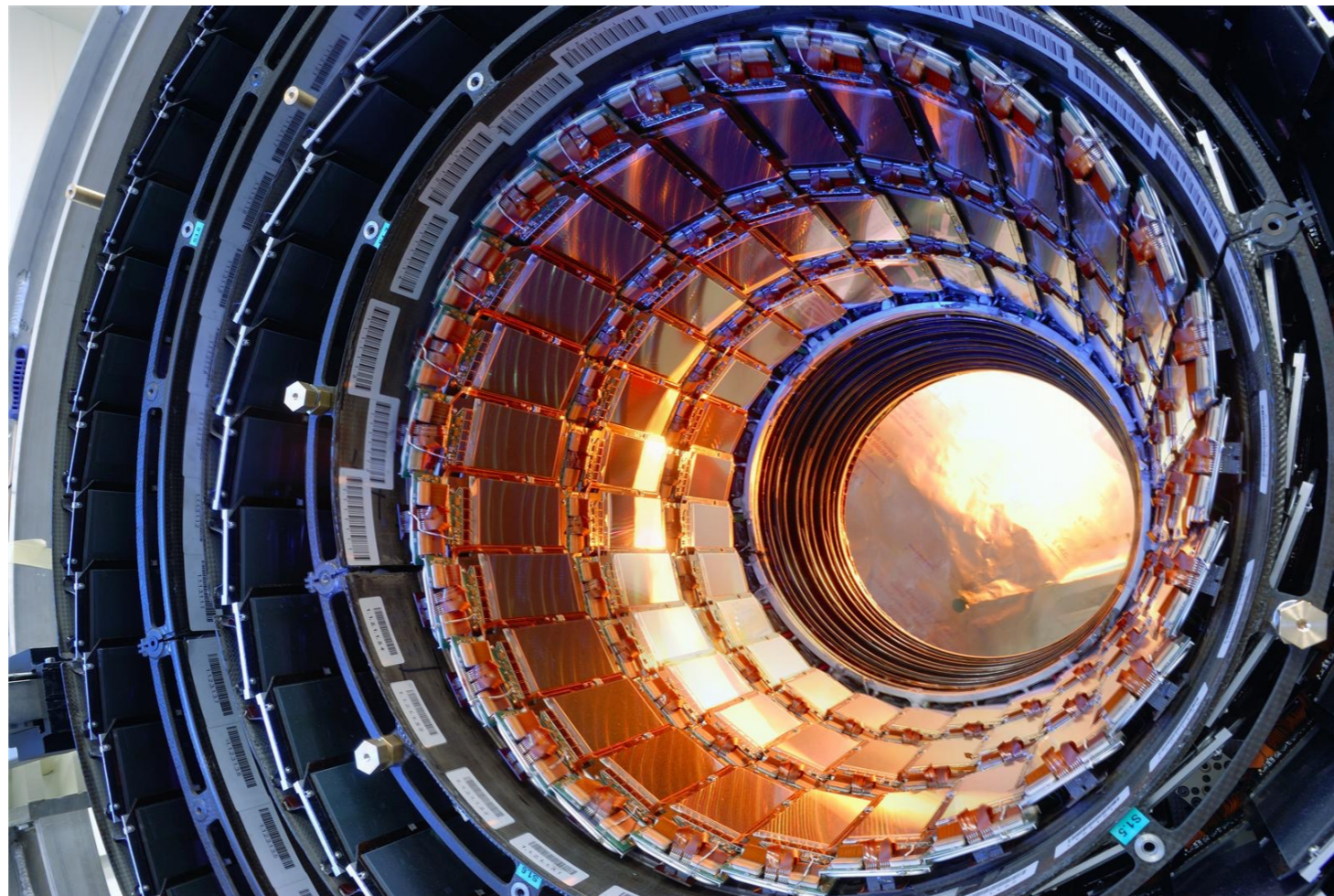
Mean Threshold of all the ROCs in one BPix sector (T=-15°C)



Vcal: digital-to-analog amplitude unit corresponding to about 65.5 electrons (offset -414 electrons)

Re-commissioning of the Strips Tracker

- a lot of work went into establishing the cooling system
- no repairs during LS1, 97.5% of modules operational at beginning of Run 2
- new software to commission detector
- new computing infrastructure, several software and firmware upgrades
- successfully commissioned and operating smoothly



> CRUZET (Cosmic RUn at ZERo Tesla) started on 10th February

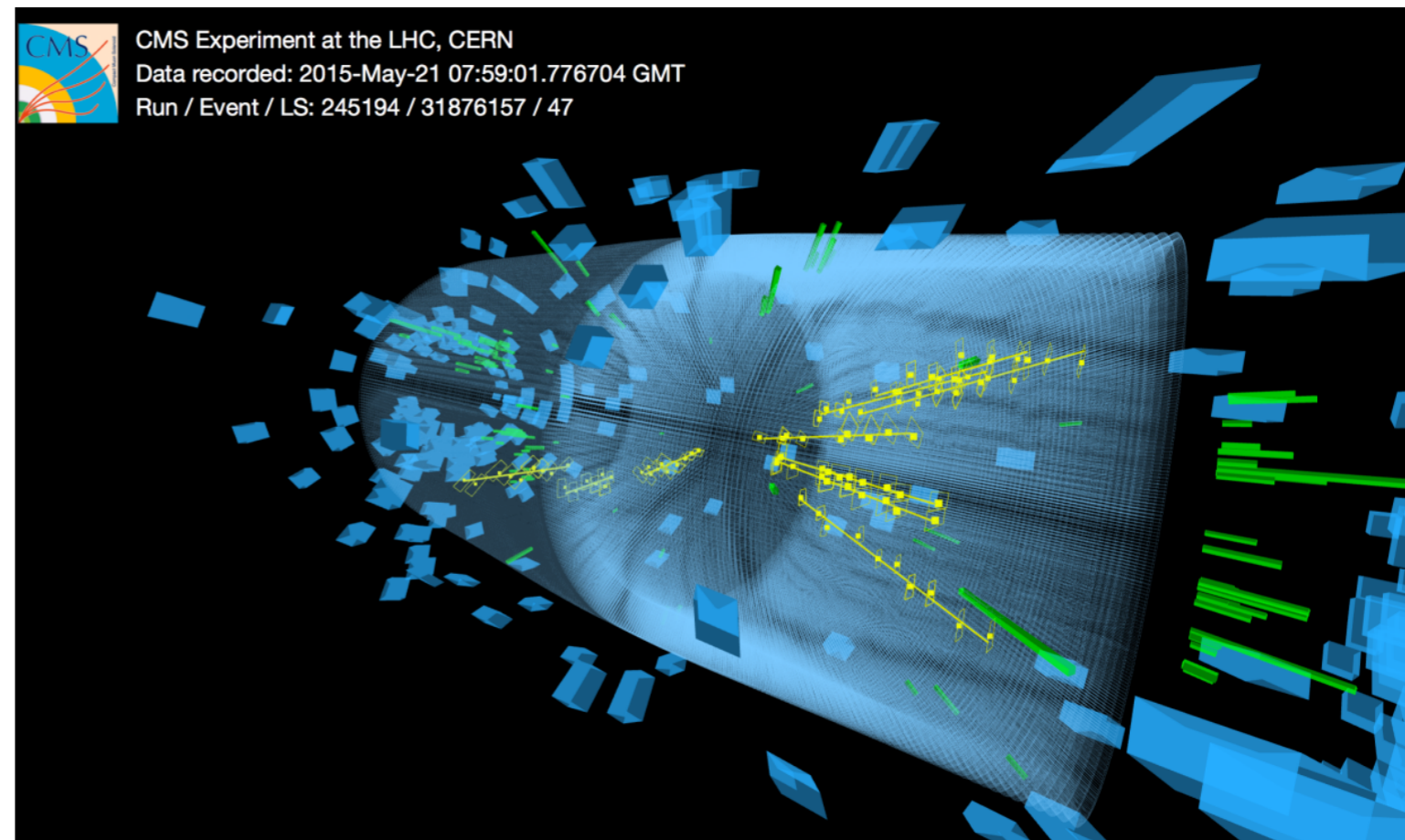
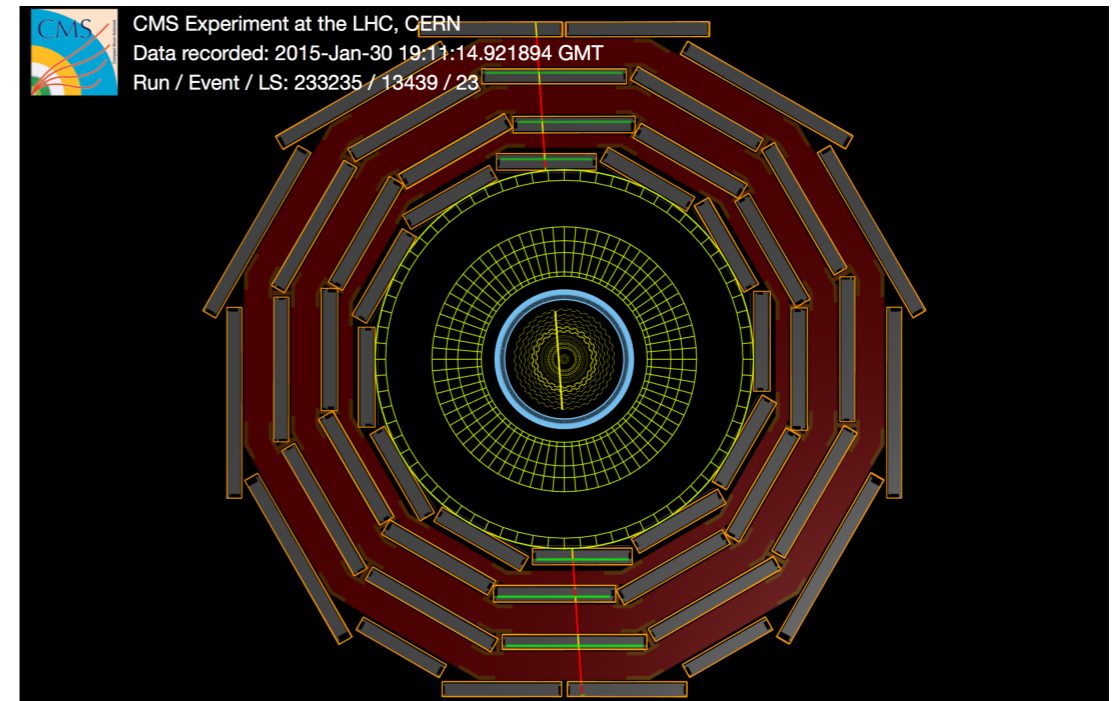
- timing scans (internal and with respect to global)
- noisy pixels masked (< 0.1%)
- 420 hours of cosmics recorded

> CRAFT (Cosmic Run At Four Tesla) started on 19th March

- recorded 3 million cosmics events (1.8 million tracks)

> 20th May: first LHC test collisions at 13 TeV centre-of-mass energy

- pixel detector off since beams not declared as stable
- strips tracker taking data



Conclusions and summary

- > first long shutdown of LHC lies behind us
- > time has been used
 - to repair the pixel detector to 99% operationality
 - to significantly improve cooling of tracking detectors
 - and for several other things...
- > both pixel detector and strips tracker are ready for the challenges of LHC Run 2

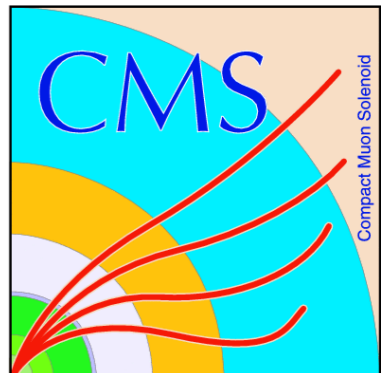




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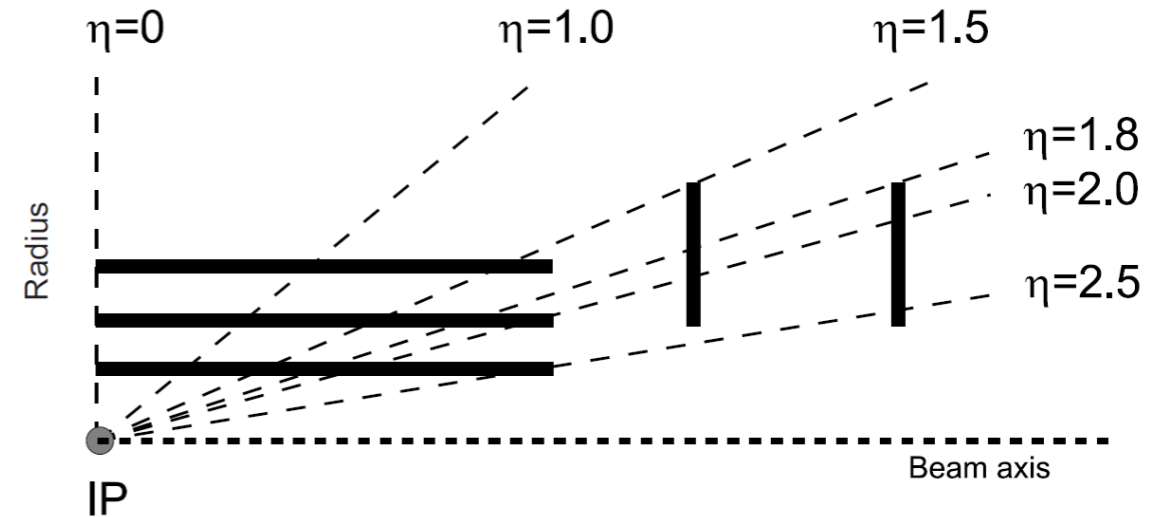
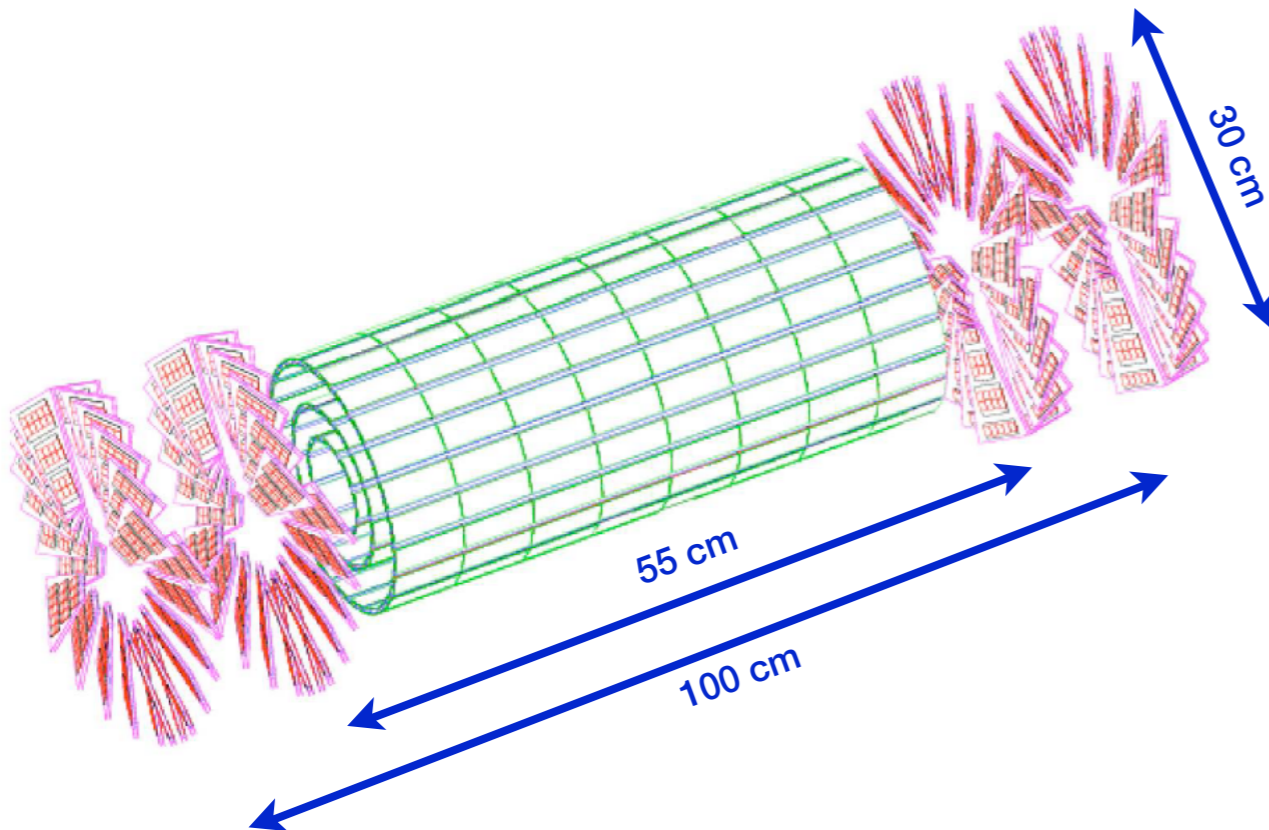
backup

additional information



design requirements:

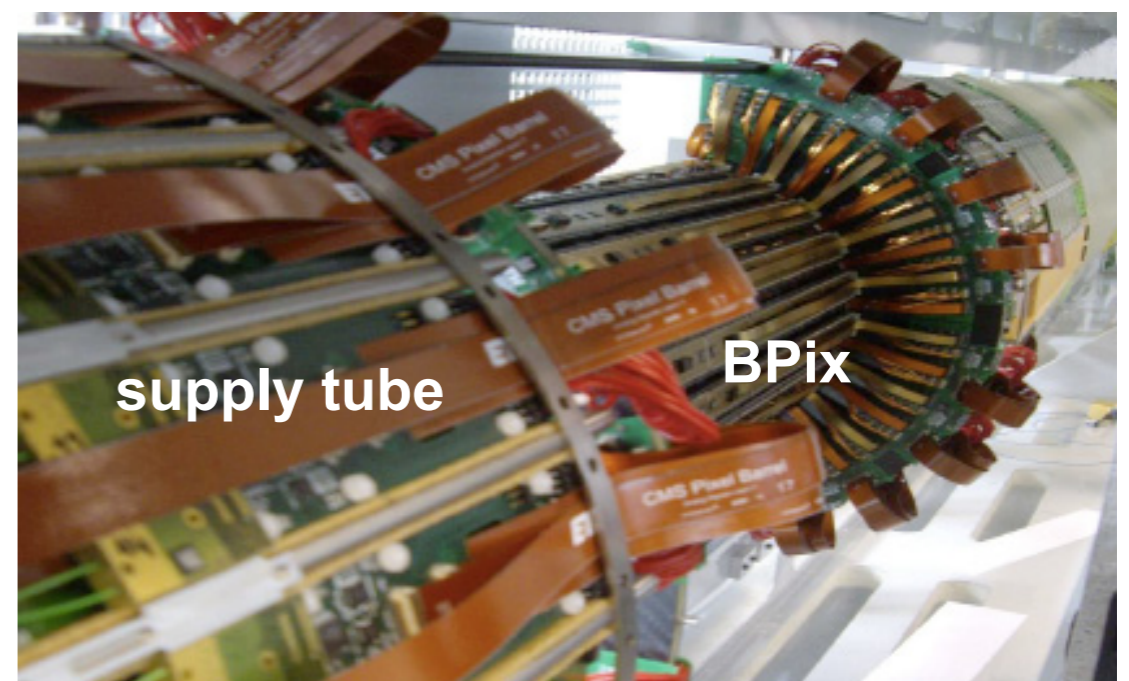
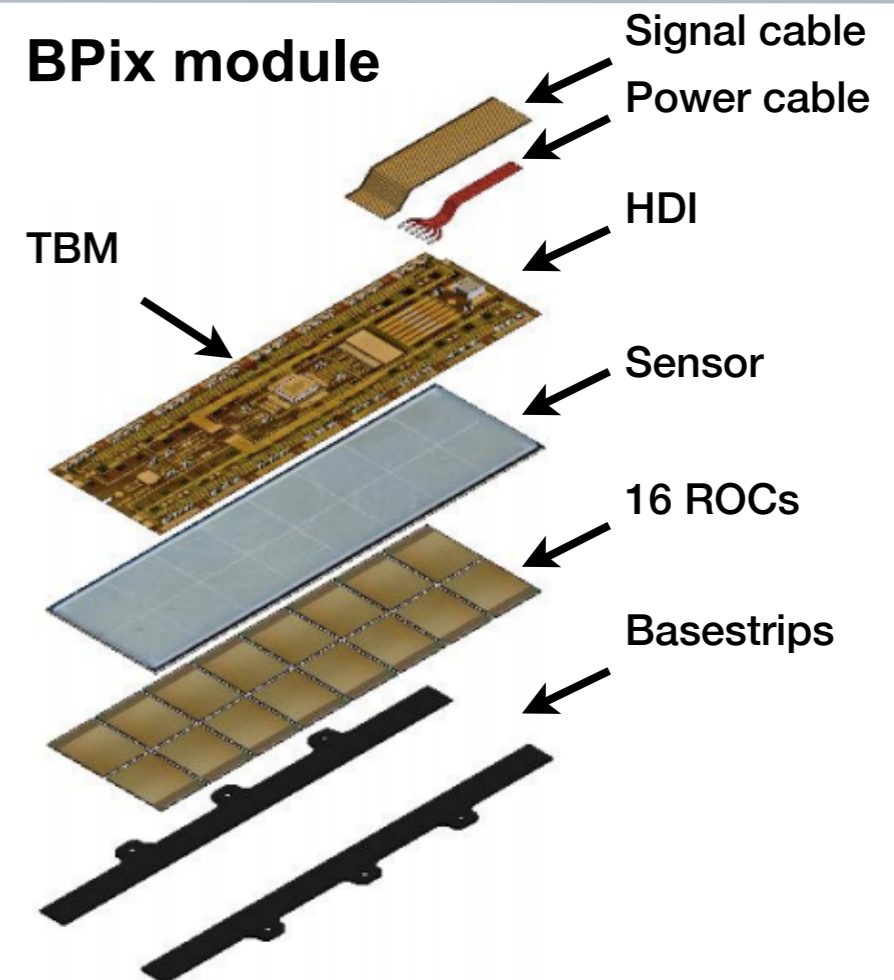
- > position resolution in $r\phi < 15 \mu\text{m}$
- > ~ 3 hits for central part of CMS detector
- > time resolution $< 25 \text{ ns}$
- > hit detection efficiency $> 97\%$



basic properties:

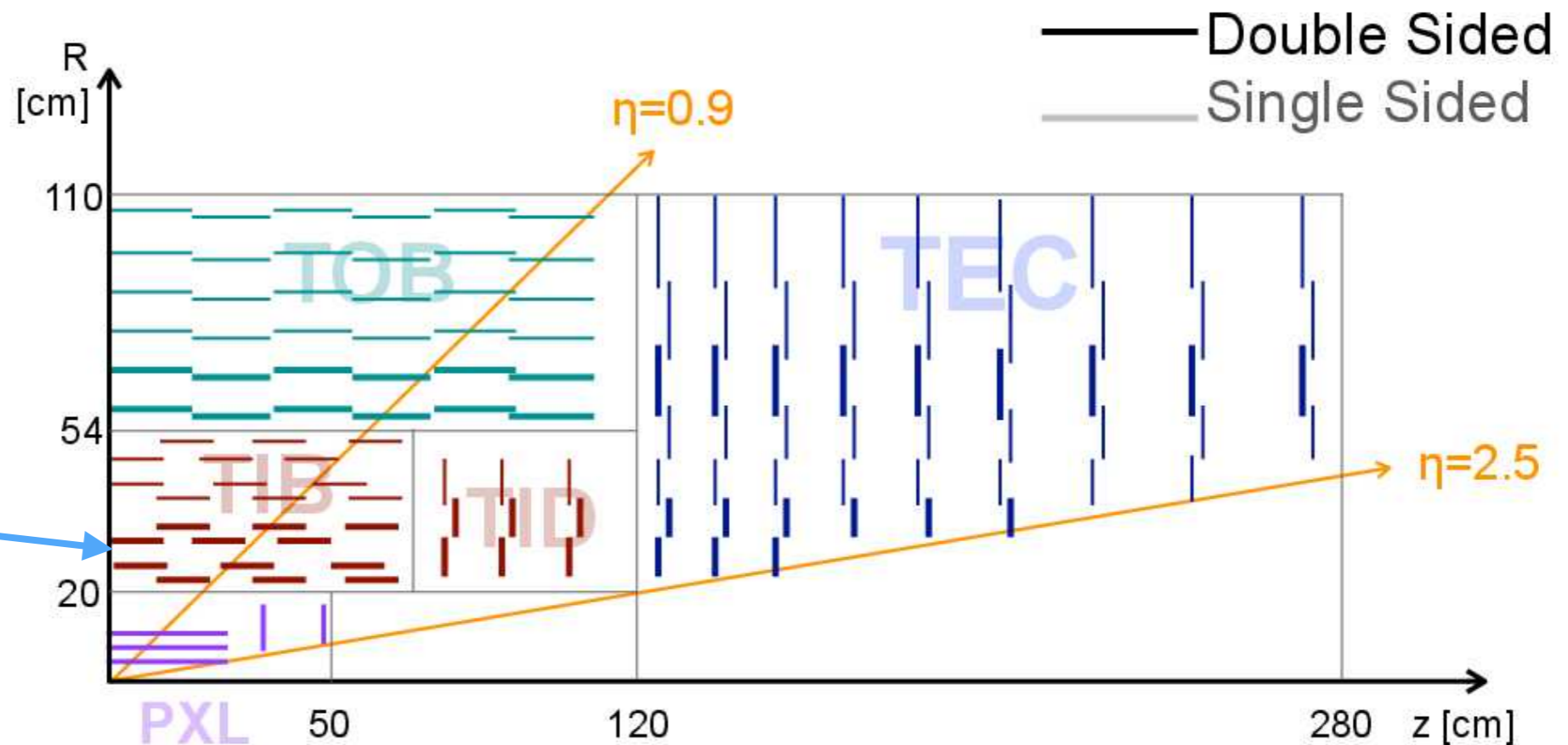
- > 3 barrel layers (BPix)
 - radii of 4.3, 7.2, and 11 cm
 - 48 million pixels, area of 0.78 m^2
- > 2 endcap pixel disks at each side (FPix)
 - longitudinal distance from centre of detector: $|z| = 34.5$ and 46.5 cm
 - 18 million pixels, area of 0.28 m^2
- > 3 hit system for $|\eta| < 2.1$ (2 hits up to $|\eta| < 2.5$)

- > BPix: 768 modules (672 full, 96 half modules), segmented into 11520 readout chips (ROCs)
- > FPix: 192 panels, 4320 ROCs
- > pixel size: 100 x 150 μm (250 μm sensor thickness)
- > 1 ROC serves a 52 x 80 array of pixels
- > sensor:
 - n+ implant in n bulk
 - bump-bonded to ROCs
- > Token Bit Manager (TBM) located on High Density Interconnect (HDI)
 - distributes clock and trigger to ROCs
 - manages ROC controls and readout
- > Analog Opto-Hybrids (AOH), cooling, power, readout boards etc. on supply tube



CMS Silicon Strip Tracker

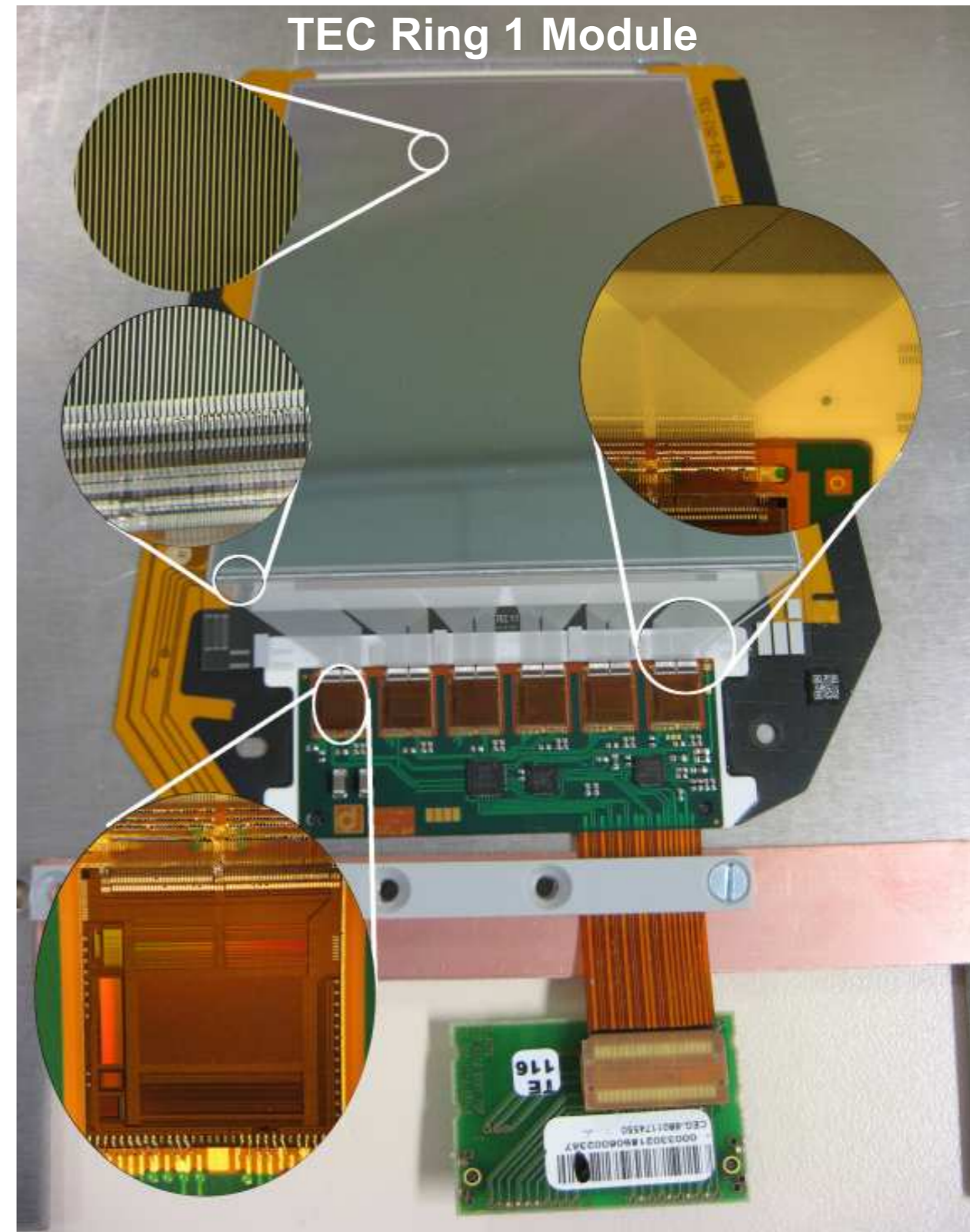
- > 10 layers in barrel region
 - 4 Inner Barrel (TIB), 6 Outer Barrel (TOB)
- > 9+3 discs in the inner disks (TID) and endcaps (TEC)
- > largest and first 'all-silicon' central tracker ever built:
 - active area 200 m², length: 5 m, diameter: 2.5 m
- > ~9.6 million electronic channels



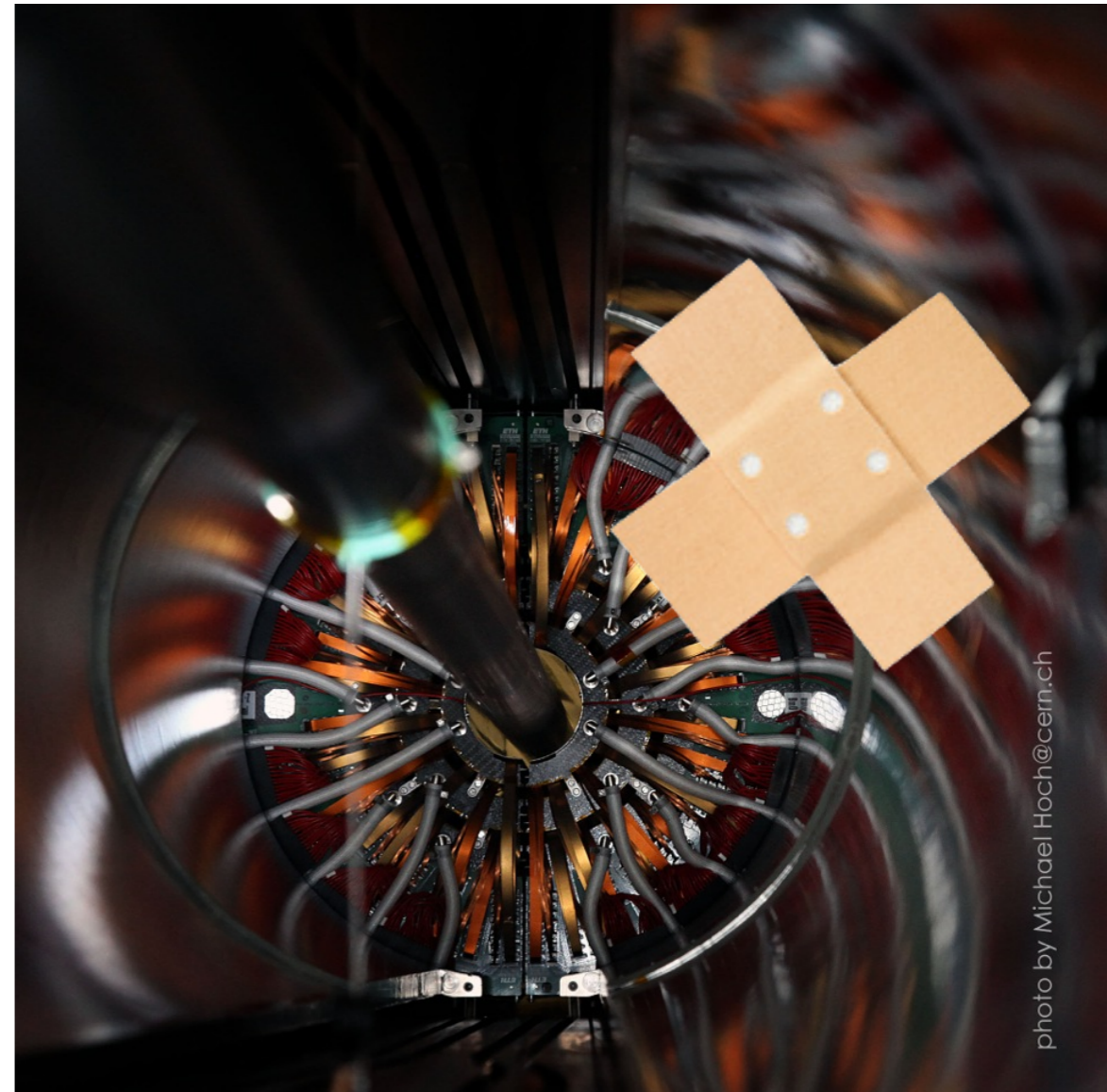
stereo modules
(two modules
with 150 mrad
stereo angle)

CMS Strip Modules

- > p⁺-in-n silicon sensors
- > 320 μm and 500 μm thick
- > 512-768 strips
- > strip pitch 83-205 μm
- > analog readout: 4-6 APV25 chips with two readout modes:
 - peak: robust timing, low noise, mostly for cosmics
 - deconvolution: fast (shorter signal), more noise, mostly for collisions
- > electronics on hybrid
- > optical links for data transfer

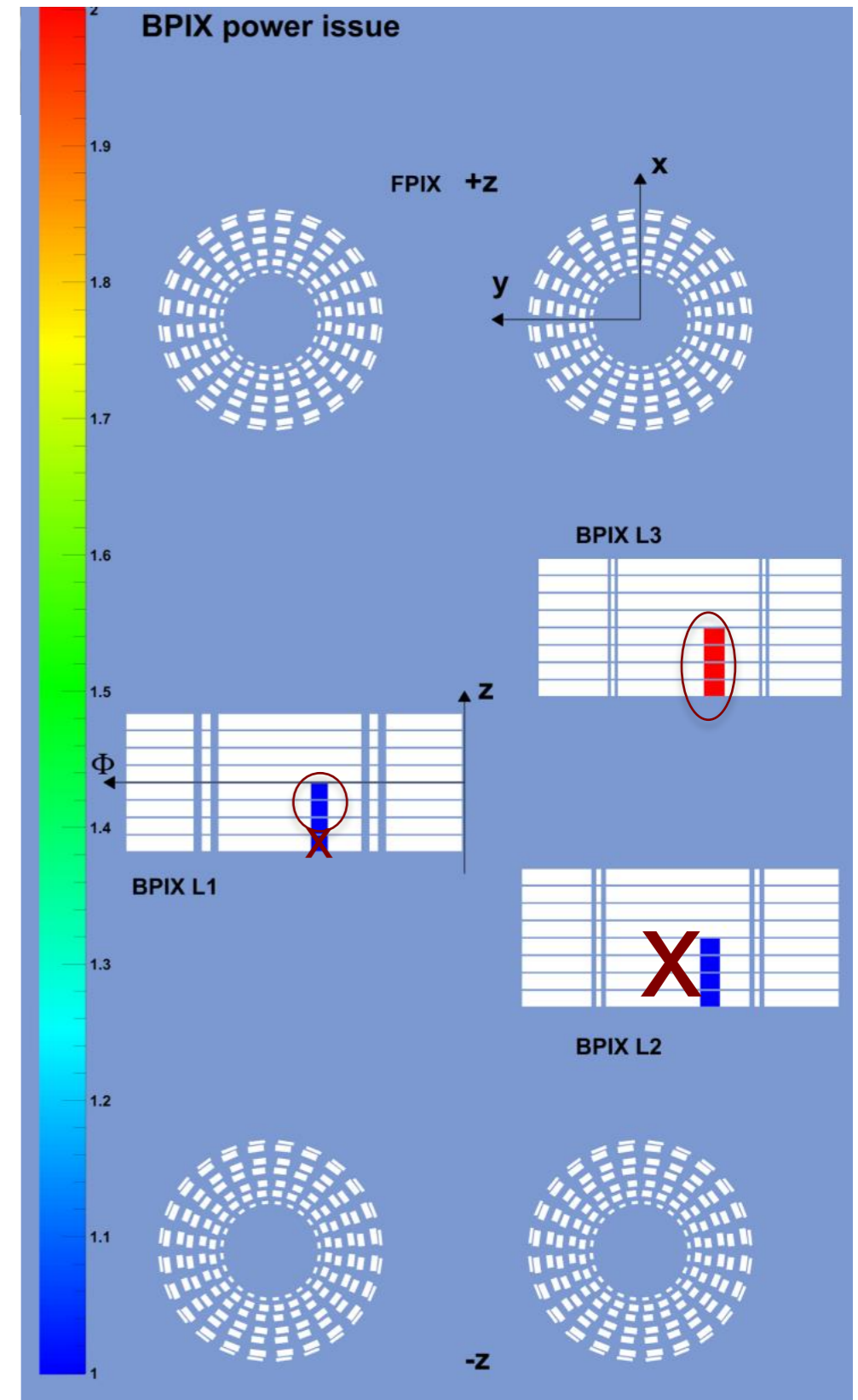


- BPix: 88 permanently disabled ROCs, namely
 - 40 ROCs because of different problems in 4 modules
 - 16 ROCs because of no high-voltage for 2 modules
 - 32 ROCs because of no hits (HV problem) in two modules
 - in total ~1% disabled channels
- FPix: 1 dead ROC, some double columns
 - in total 0.04% dead channels



> currently biggest problem: BmO sector 3, layers 1+2 (~1.6% of BPix, ~22.5° in ϕ):

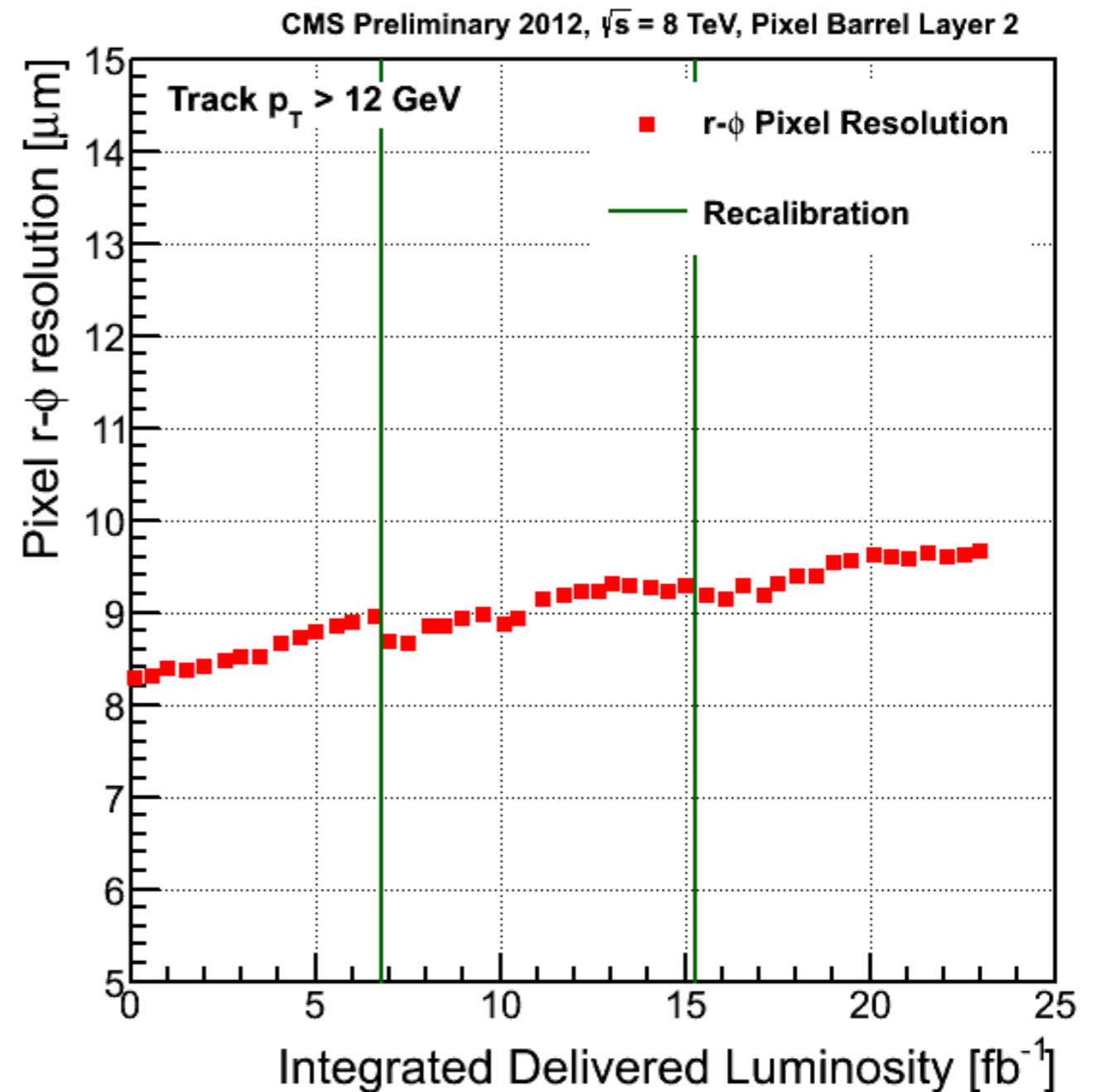
- configuring front-end leads to under-voltage of control power supply
- Delay25 gets reset, but not PLL
- problem only observed in presence of B-field
- cosmics with magnet were taken with layer 3 powered only
- several weeks spent investigating the problem, but still no solution found
- currently best option: full layer 3 (12 modules) + 3 (out of 4) modules of layer 1
- will also try again to increase current limit for control power supply to prevent under-voltage



Pixel bias voltage increase

➤ BPix bias voltage increased from 150V to 200V - FPix to remain at 300V

- loss of position resolution observed in 2012
- signs of charge trapping/incomplete charge collection
- disadvantage of smaller Lorentz angle, but still larger than charge sharing pitch





How to deal with high data rates and radiation?

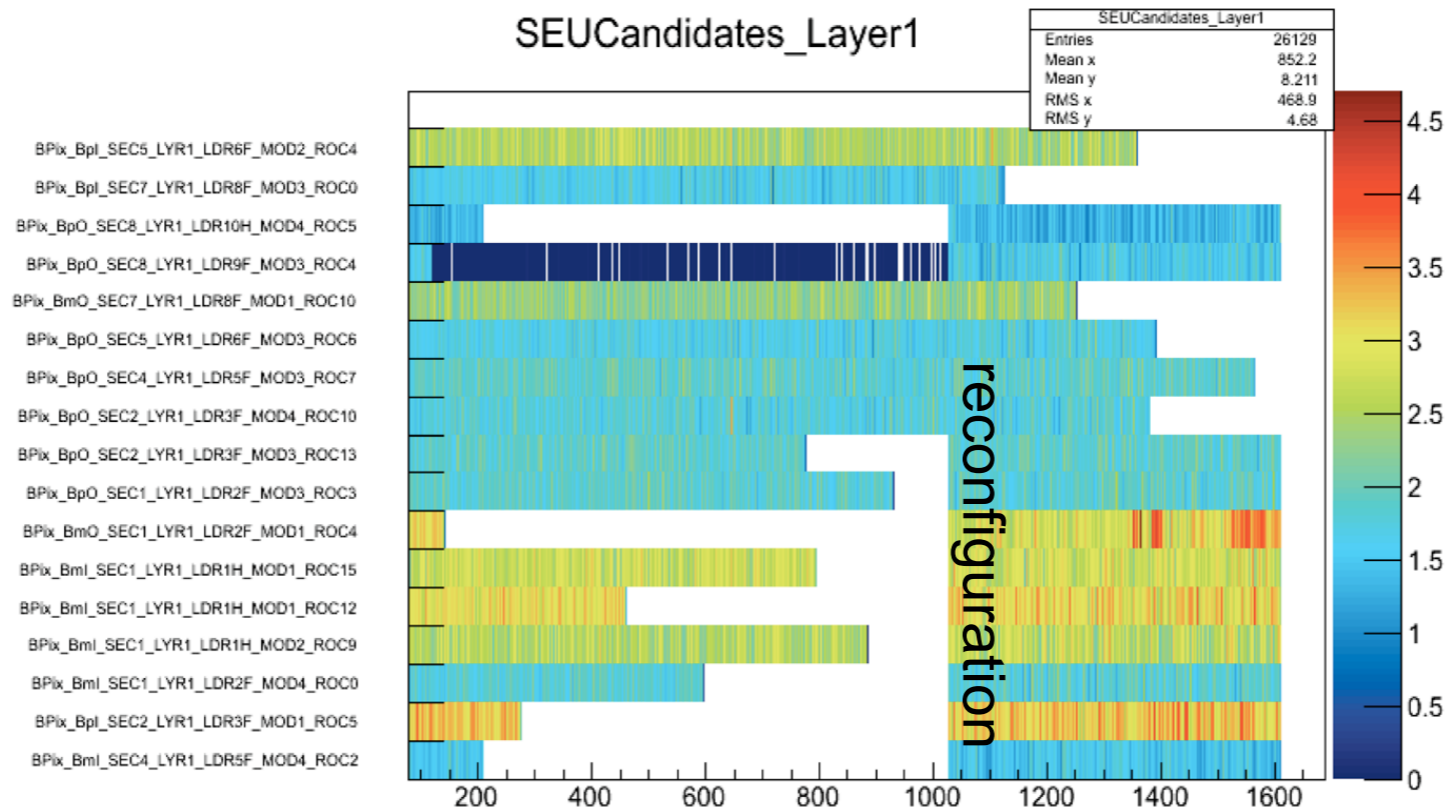
- > operate at lower temperature
- > upgrade of the DAQ surface links
 - link after the slink, i.e. from the FRL, was changed from Myrinet to 10Gb ethernet
- > centring of BPix w.r.t. beam pipe → rates are more equal
- > SEU recovery in place
- > frequent re-calibrations

> Single Event Upset (SEUs): bit flip on detector electronics caused by irradiation

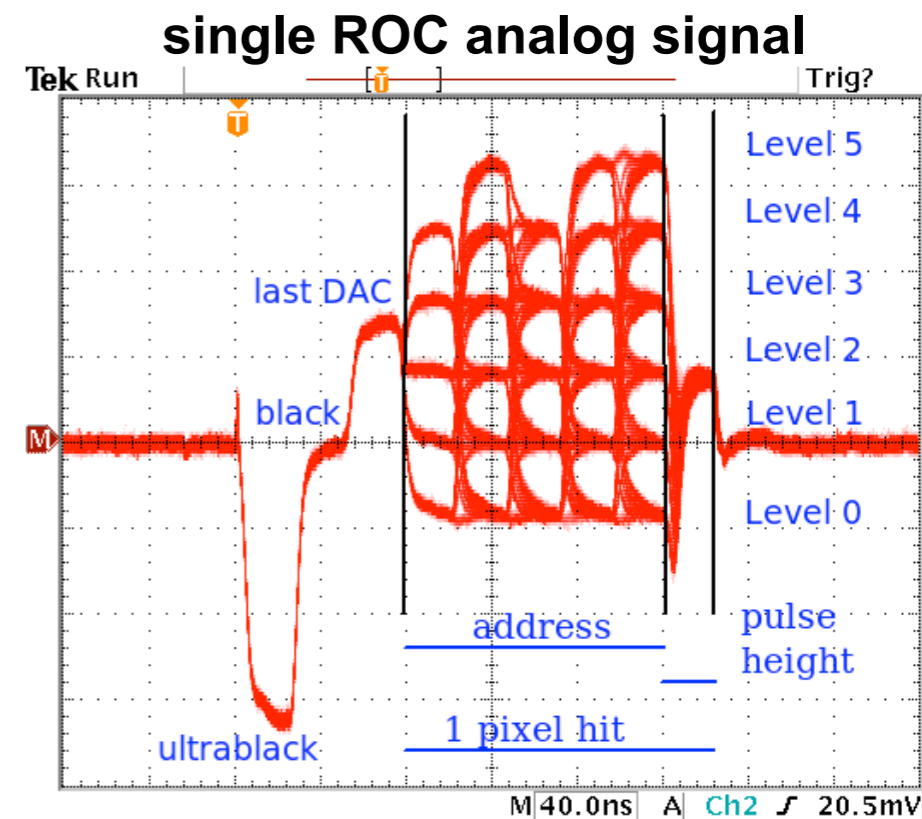
- can affect control registers at different levels: from pixels to auxiliary electronics
- no action needed if single pixel or ROC affected
- immediate action taken if SEU stops data-flowing from a full module (>1‰)
- happens ~every 73 pb⁻¹

> automatic SEU identification and recovery mechanism implemented

- takes a few seconds (used to take ~3/4 minutes)
- takes advantage of the recovery triggered by other systems to perform reprogramming



- > Pixel Detector functioning depends on readout chain settings
- > optimal settings for readout system parameters must be used
- > majority of settings unchanged until:
 - detector temperature changes
 - significant amount of radiation is accumulated
- > for parameters more sensitive to environmental changes, recalibration performed on regular basis:
 - Front-End Driver(FED) opto-receiver offset adjustment (weekly)
 - set the signal baseline in the middle of ADC range
- > address level calibration (monthly):
 - ensure good decoding of pixel address by FED



pixel address level distribution

